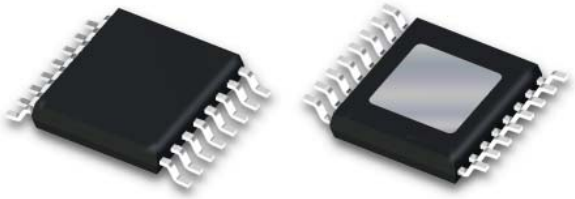
Wide Input Voltage Range, High Efficiency Fault Tolerant LED Driver

Features and Benefits

- Wide input voltage range: 5 to 40 V
- Maximum LED current of 120 mA
- TSSOP-16 (LP) package; exposed pad offers best-in-class thermal performance
- Typical LED accuracy of 0.5%, and 0.5% for LED-to-LED matching
- Internal bias supply for single-supply operation (typically between V_{IN} = 8 to 24 V)
- Integrated boost converter with 60 V DMOS switch with overvoltage protection (OVP)
- Drives up to 12 series LEDs in 2 parallel strings
- Single PWM pin interface for both PWM dimming and enable function
- Sync function to synchronize boost converter switching frequencies up to 2.25 MHz, this gives the designer the ability minimize component size
- Provides driver for external PMOS input disconnect switch
- Protection features:
  - Open or shorted V_{LED} pin protection
  - Open Schottky protection
  - Cycle-by-cycle current limit
  - Overtemperature protection (OTP)
  - Output short circuit protection

Package: 16-pin TSSOP with exposed thermal pad (suffix LP)



Not to scale

Description

The A8515 is a multi-output white LED (WLED) driver for LCD backlighting in consumer and industrial displays. It integrates a current-mode boost converter with an internal power DMOS switch and two current sinks. The boost converter can drive up to 24 LEDs: 12 LEDs per string at 120 mA. The LED sinks can be paralleled together to achieve higher LED currents, up to 240 mA. The A8515 can operate from a single power supply, from 5 to 40 V.

PWM dimming is implemented with an external PWM input signal. The PWM dimming pin is used to control the LED intensity by using pulse width modulation.

The low, 720 mV regulation voltage on the LED current sources reduces power loss and improves efficiency.

The A8515 is provided in a 16-pin TSSOP package (suffix LP) with an exposed thermal pad. It is lead (Pb) free, with 100% matte tin leadframe plating.

Applications

- Desktop LCD flat panel displays (FPD)
- Flat panel video displays
- LCD TVs and monitors

Typical Application Diagram

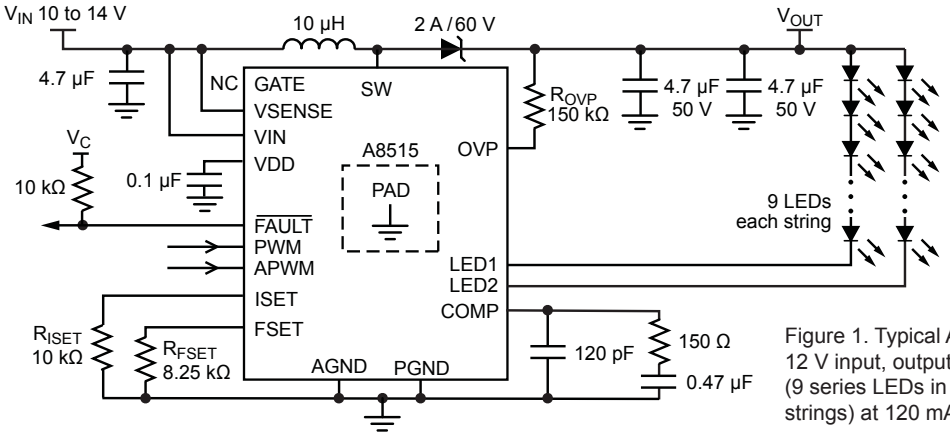


Figure 1. Typical Application Circuit; 12 V input, output to 18 LEDs (9 series LEDs in each of two strings) at 120 mA each.

Selection Guide

Part Number	Packing
A8515GLPTR-T	4000 pieces per 13-in. reel

Absolute Maximum Ratings*

Characteristic	Symbol	Notes	Rating	Unit
LEDx Pin			–0.3 to 55	V
OVP Pin			–0.3 to 60	V
VIN, VSENSE, GATE Pins		V_{SENSE} should not exceed V_{IN} by more than ±0.4 V. GATE cannot exceed V_{IN} by more than 0.4 .V	–0.3 to 40	V
SW Pin		Continuous	–0.6 to 62	V
		t < 50 ns	–1.0	V
$\overline{\text{FAULT}}$ Pin			–0.3 to 40	V
ISET, FSET, APWM Pins			–0.3 to 5.5	V
All other pins			–0.3 to 7	V
Operating Ambient Temperature	T_A	Range G	–40 to 105	ºC
Maximum Junction Temperature	T_J(max)		150	ºC
Storage Temperature	T_{stg}		–55 to 150	ºC

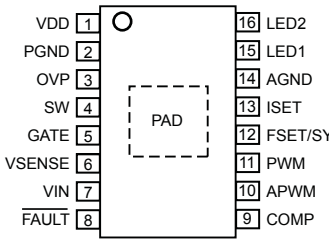
*Stresses beyond those listed in this table may cause permanent damage to the device. The Absolute Maximum ratings are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the Electrical Characteristics table is not implied. Exposure to Absolute-Maximum-rated conditions for extended periods may affect device reliability.

Thermal Characteristics may require derating at maximum conditions

Characteristic	Symbol	Test Conditions*	Value	Unit
Package Thermal Resistance	$R_{\theta JA}$	On 4-layer PCB based on JEDEC standard	34	ºC/W
		On 2-layer PCB with 1 in.^{2} of copper area each side	52	ºC/W

*Additional thermal information available on the Allegro website

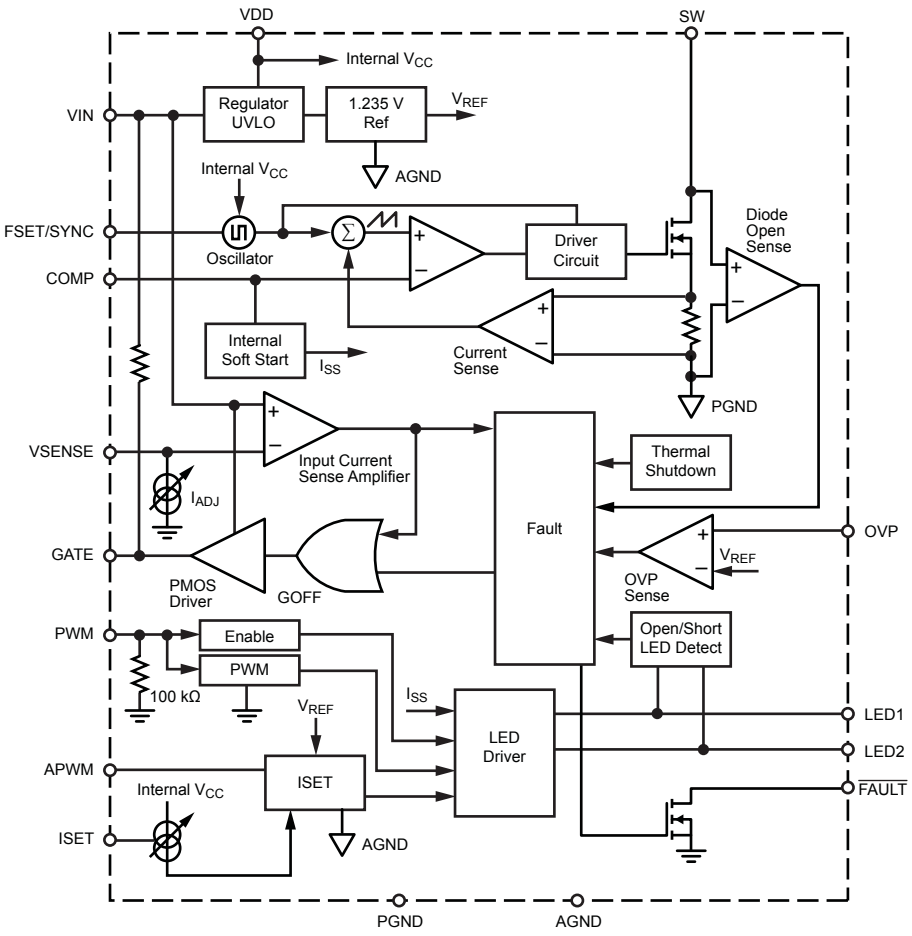
Pin-out Diagram



Terminal List Table

Number	Name	Function
1	VDD	Output of internal LDO; connect a 0.1 µF decoupling capacitor between this pin and GND.
2	PGND	Power ground for internal NMOS device.
3	OVP	This pin is used to sense an overvoltage condition; connect the R_{OVP} resistor from V_{OUT} to this pin to adjust the Overvoltage Protection function (OVP).
4	SW	The drain of the internal NMOS switch of the boost converter.
5	GATE	Output gate driver pin for external P-channel FET control.
6	VSENSE	Connect this pin to the negative sense side of the current sense resistor R_{SC}; the threshold voltage is measured as $V_{IN} - V_{SENSE}$.
7	VIN	Input power to the A8515 as well as the positive input used for the current sense resistor.
8	$\overline{\text{FAULT}}$	This pin is used to indicate a fault condition, it is an open drain type configuration that will be pulled low when a fault occurs; connect a 100 kΩ resistor between this pin and the required logic level voltage.
9	COMP	Output of the error amplifier and compensation node; connect a series R_ZC_Z network from this pin to GND for control loop compensation.
10	APWM	Analog trimming option or dimming; applying a digital PWM signal to this pin adjusts the internal I_{SET} current.
11	PWM	PWM dimming pin used to control the LED intensity by using pulse width modulation; the typical PWM dimming frequency is in the range of 200 Hz to 1 kHz.
12	FSET /SYNC	Frequency/synchronization pin; connect a resistor R_{FSET} from this pin to GND to set the switching frequency. This pin can also be used to synchronize two or more converters in the system; the maximum synchronization frequency is 2.3 MHz.
13	ISET	Connect the R_{ISET} resistor between this pin and GND to set the LED 100% current level.
14	AGND	LED signal ground.
15	LED1	Connect the cathode of the LED string to this pin.
16	LED2	Connect the cathode of the LED string to this pin.
–	PAD	Exposed pad of the package providing enhanced thermal dissipation; this pad must be connected to the ground plane(s) of the PCB with at least 8 thermal vias, directly in the pad.

Functional Block Diagram



ELECTRICAL CHARACTERISTICS[1] Valid at V_{IN} = 16 V, T_A = 25°C, • indicates specifications guaranteed by design and characterization over the full operating temperature range with $T_A = T_J$ = –40°C to 105°C; unless otherwise noted

Characteristics	Symbol	Test Conditions		Min.	Typ.[2]	Max.	Unit
Input Voltage Specifications							
Operating Input Voltage Range	V_{IN}		•	5	–	40	V
UVLO Start Threshold	$V_{UVLOrise}$	V_{IN} rising	•	–	–	4.35	V
UVLO Stop Threshold	$V_{UVLOfall}$	V_{IN} falling	•	–	–	3.90	V
UVLO Hysteresis[3]	$V_{UVLOHYS}$			–	400	–	mV
Input Currents							
Input Quiescent Current	I_Q	EN = V_{IH}; SW = 2 MHz, no load		–	15	–	mA
Input Sleep Supply Current	I_{QSLEEP}	V_{IN} = 16 V, V_{EN} / PWM = SYNC = 0 V		–	3.5	10.0	µA
Input Logic Levels (EN/PWM/APWM)							
Input Logic Level-Low	V_{IL}	5 V < V_{IN} < 40 V		–	–	400	mV
Input Logic Level-High	V_{IH}	5 V < V_{IN} < 40 V		1.5	–	–	V
EN/PWM Pins Open Drain Pull-down Resistor	R_{EN}			–	100	–	kΩ
APWM Pull-down Resistor	R_{APWM}	EN = V_{IH}		–	100	–	kΩ
APWM							
APWM Frequency	f_{APWM}	APWM, V_{IH} = 1.5 V, V_{IL} = 0.4 V		20	–	1000	kHz
Error Amplifier							
Open Loop Voltage Gain	A_{VOL}			–	47	–	dB
Transconductance	gm	ΔI_{COMP} = ±10 µA		–	990	–	µA/V
Source Current	$I_{EA(SRC)}$	V_{COMP} = 1.5 V		–	–360	–	µA
Sink Current	$I_{EA(SINK)}$	V_{COMP} = 1.5 V		–	360	–	µA
COMP Pin Pull-down Resistance	R_{COMP}	$\overline{FAULT}$ = 1		–	2000	–	Ω
Overvoltage Protection							
Overvoltage Threshold	$V_{OVP(th)}$	OVP connected to V_{OUT}		7.6	8	8.4	V
OVP Sense Current	I_{OVPH}			190	200	210	µA
OVP Leakage Current	I_{OVPLKG}	R_{OVP} = 40.2 kΩ, V_{IN} = 16 V, EN = V_{IL}		–	0.1	1	µA
Secondary Overvoltage Protection	$V_{OVP(sec)}$			–	55.5	–	V
Boost Switch							
Switch On-Resistance	R_{SW}	I_{SW} = 0.750 A, V_{IN} = 16 V		–	300	–	mΩ
Switch Leakage Current	I_{SWLKG}	V_{SW} = 16 V, PWM = V_{IL}		–	0.1	1	µA
Switch Current Limit	$I_{SW(LIM)}$			3.0	3.4	3.8	A
Secondary Switch Current Limit[2]	$I_{SW(LIM2)}$	Higher than $I_{SW(LIM)}$(max) for all conditions, device latches when detected		–	7	–	A
Soft Start Boost Current Limit	$I_{SWSS(LIM)}$	Initial soft start current for boost switch		–	700	–	mA
Minimum Switch On-Time	$t_{SWONTIME}$			–	85	–	ns
Minimum Switch Off-Time	$t_{SWOFFTIME}$			–	85	–	ns

Continued on the next page…

ELECTRICAL CHARACTERISTICS[1] (continued) Valid at V_{IN} = 16 V, T_A = 25°C, • indicates specifications guaranteed by design and characterization over the full operating temperature range with $T_A = T_J$ = –40°C to 105°C; unless otherwise noted

Characteristics	Symbol	Test Conditions		Min.	Typ.[2]	Max.	Unit
Oscillator Frequency							
Oscillator Frequency	f_{SW}	R_{FSET} = 10 kΩ	•	1.8	2	2.2	MHz
		R_{FSET} = 20 kΩ		–	1	–	MHz
		R_{FSET} = 35.6 kΩ		–	600	–	kHz
FSET Pin Voltage	V_{FSET}	R_{FSET} = 10 kΩ		–	1.00	–	V
FSET Frequency Range	f_{FSET}			600	–	2500	kHz
Synchronization							
Synchronized PWM Frequency	f_{SWSYNC}			600	–	2250	kHz
Synchronization Input Minimum Off-Time	$t_{PWSYNCOFF}$			150	–	–	ns
Synchronization Input Minimum On-Time	$t_{PWSYNCON}$			150	–	–	ns
LED Current Sinks							
LEDx Accuracy	Err_{LED}	I_{SET} = 120 µA	•	–	0.5	2	%
LEDx Matching	ΔLEDx	I_{SET} = 120 µA	•	–	0.5	1	%
LEDx Regulation Voltage	V_{LED}	$V_{LED1} = V_{LED2}$, I_{SET} = 120 µA		–	720	–	mV
I_{SET} to I_{LEDx} Current Gain	A_{ISET}	I_{SET} = 120 µA	•	960	980	1000	A/A
ISET Pin Voltage	V_{ISET}			–	1.003	–	V
Allowable ISET Current	I_{SET}		•	40	–	125	µA
V_{LED} Short Detect	V_{LEDSC}	While LED sinks are in regulation, sensed from LEDx pin to GND		4.6	–	–	V
Soft Start LEDx Current	I_{LEDSS}	Current through each enabled LEDx pin during soft start		–	3.0	–	mA
Maximum PWM Dimming Until Off-Time	t_{PWML}	Measured while EN = low, during dimming control and internal references are powered-on (exceeding t_{PWML} results in shutdown)		–	32750	–	f_{SW} cycles
Minimum PWM On-Time	t_{PWMH}	First cycle when powering-up device		–	0.75	2	µs
PWM High to LED-On Delay	$t_{dPWM(on)}$	Time between PWM enable and LED current reaching 90% of maximum		–	0.5	1	µs
PWM Low to LED-Off Delay	$t_{dPWM(off)}$	Time between PWM enable going low and LED current reaching 10% of maximum		–	–	500	ns
GATE Pin							
Gate Pin Sink Current	I_{GSINK}	V_{GS} = 0 V with respect to V_{IN}		–	−100	–	µA
Gate Fault Shutdown Greater than 2X Current	$t_{GFAULTT2}$			–	–	3	µs
Gate Voltage	V_{GS}	Gate to source voltage measured when gate is on		–	-6.6	–	V

Continued on the next page…

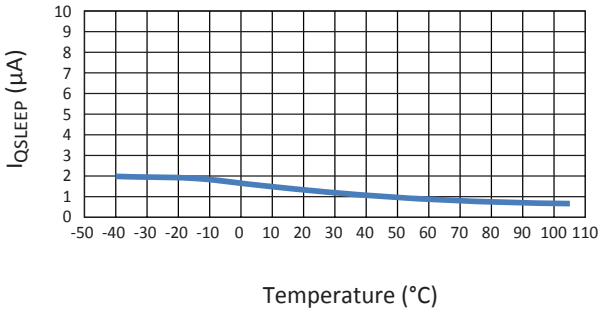
ELECTRICAL CHARACTERISTICS[1] (continued) Valid at V_{IN} = 16 V, T_A = 25°C, • indicates specifications guaranteed by design and characterization over the full operating temperature range with $T_A = T_J$ = –40°C to 105°C; unless otherwise noted

Characteristics	Symbol	Test Conditions		Min.	Typ.[2]	Max.	Unit
VSENSE Pin							
VSENSE Pin Sink Current	I_{ADJ}			19	20.5	22	µA
VSENSE Trip Point	$V_{SENSEtrip}$	Measured between VIN and VSENSE, R_{ADJ} = 0 Ω		–	102	–	mV
VSENSE 2X Trip	$V_{SENSEtrip2}$	2X $V_{SENSEtrip}$, instantaneous shutdown, R_{ADJ} = 0 Ω		188	204	220	mV
$\overline{\text{FAULT}}$ Pin							
$\overline{\text{FAULT}}$ Pull-Down Voltage	V_{FAULT}	I_{FAULT} = 1 mA (400 Ω)		–	–	0.4	V
$\overline{\text{FAULT}}$ Pin Leakage Current	$I_{FAULTLKG}$	V_{FAULT} = 5 V		–	–	1	µA
Thermal Protection (TSD)							
Thermal Shutdown Threshold[3]	T_{SD}	Temperature rising		–	165	–	ºC
Thermal Shutdown Hysteresis[3]	T_{SDHYS}			–	20	–	ºC

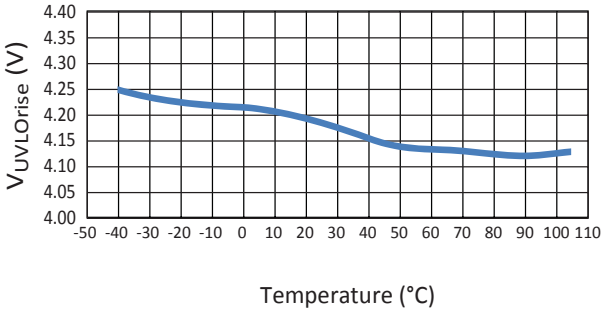
[1]For input and output current specifications, negative current is defined as coming out of the node or pin (sourcing); positive current is defined as going into the node or pin (sinking).
[2]Typical specifications are at T_A = 25ºC.
[3]Ensured by design and characterization, not production tested.

Characteristic Performance

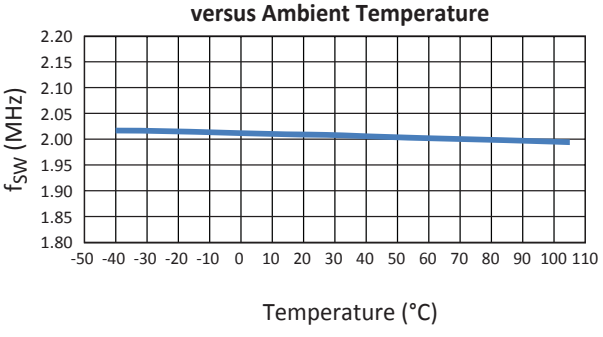
VIN Input Sleep Mode Current versus Ambient Temperature



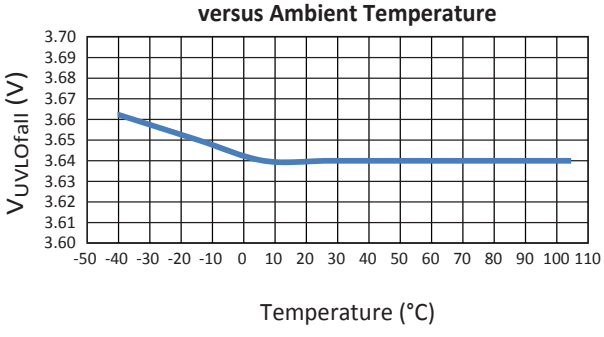
VIN UVLO Start Threshold Voltage versus Ambient Temperature



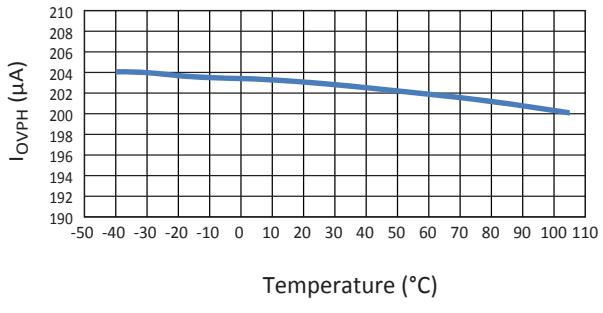
Switching Frequency versus Ambient Temperature



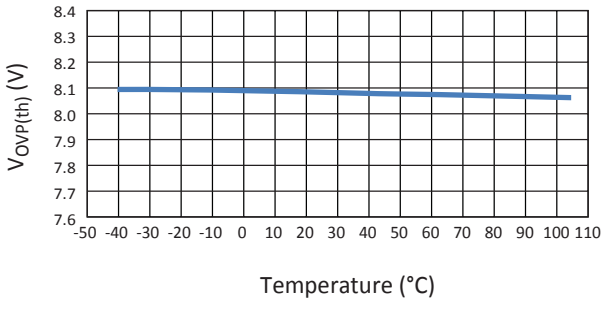
VIN UVLO Stop Threshold Voltage versus Ambient Temperature



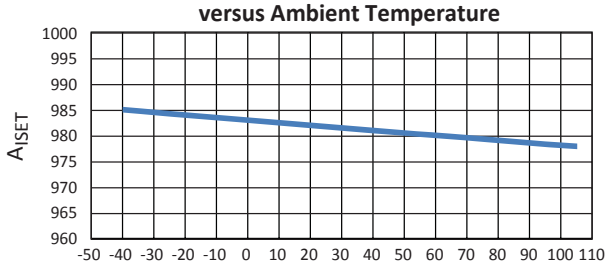
OVP Pin Sense Current versus Ambient Temperature



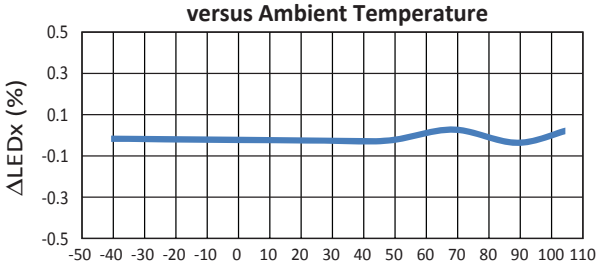
OVP Pin Overvoltage Threshold versus Ambient Temperature



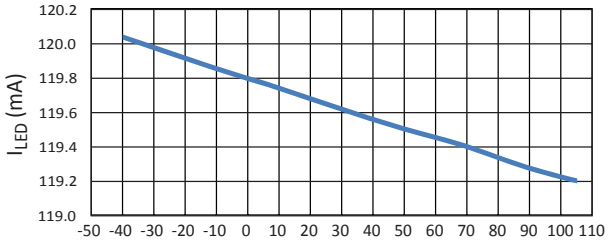
ISET to LED Current Gain versus Ambient Temperature



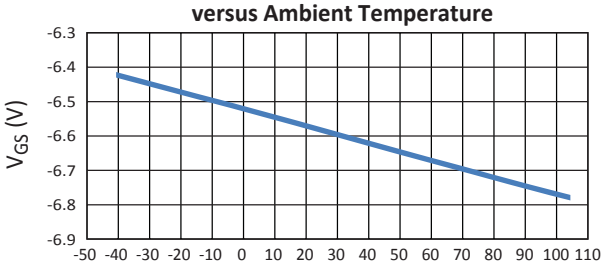
LED to LED Matching Accuracy versus Ambient Temperature



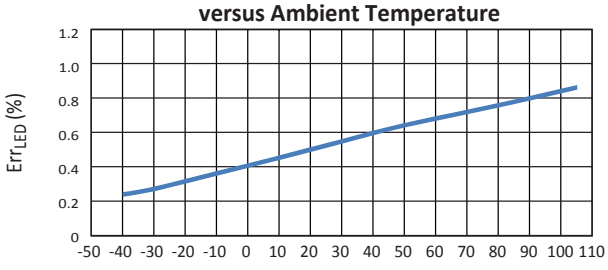
LED Current versus Ambient Temperature
I_{SET} = 120 µA



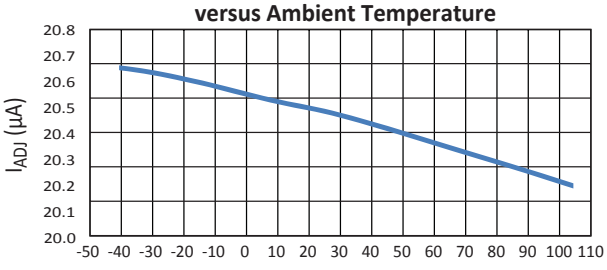
Input Disconnect Switch Gate to Source Voltage versus Ambient Temperature

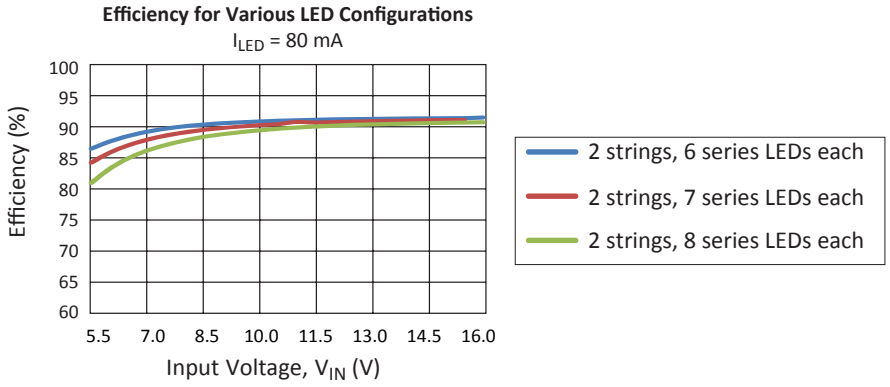


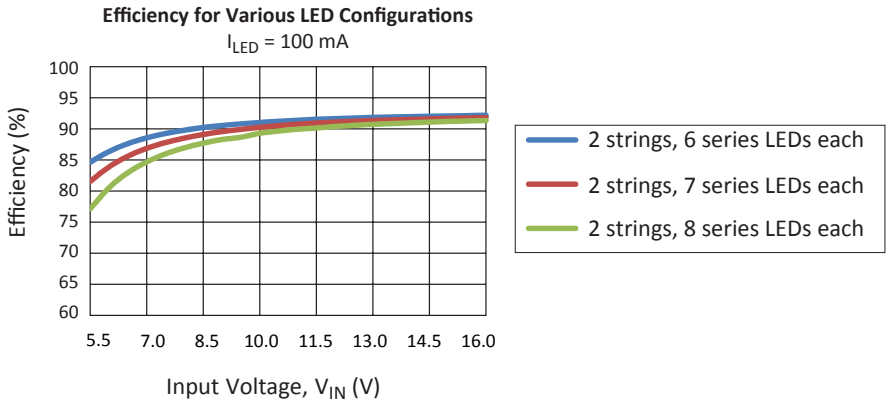
LED Current Setpoint Accuracy versus Ambient Temperature

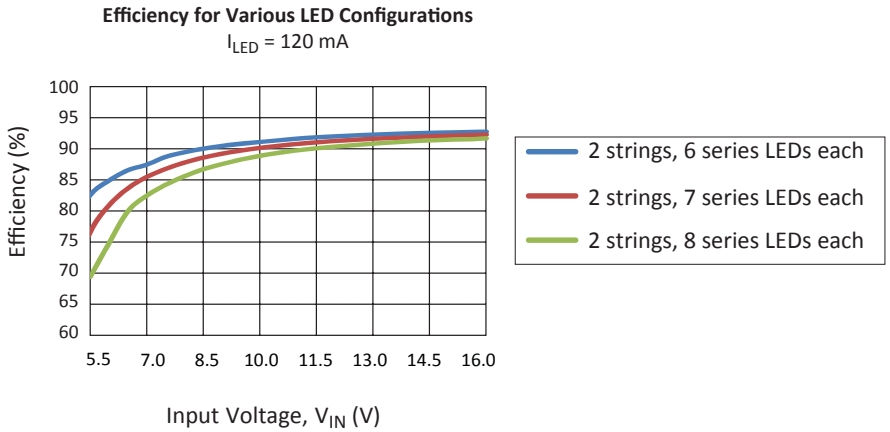


VSENSE Pin Sink Current versus Ambient Temperature




Efficiency for Various LED Configurations
I_{LED} = 80 mA
Efficiency (%)
100
95
90
85
80
75
70
65
60
5.5
7.0
8.5
10.0
11.5
13.0
14.5
16.0
Input Voltage, V_{IN} (V)
2 strings, 6 series LEDs each
2 strings, 7 series LEDs each
2 strings, 8 series LEDs each


Efficiency for Various LED Configurations
I_{LED} = 100 mA
Efficiency (%)
100
95
90
85
80
75
70
65
60
5.5
7.0
8.5
10.0
11.5
13.0
14.5
16.0
Input Voltage, V_{IN} (V)
2 strings, 6 series LEDs each
2 strings, 7 series LEDs each
2 strings, 8 series LEDs each


Efficiency for Various LED Configurations
I_{LED} = 120 mA
Efficiency (%)
100
95
90
85
80
75
70
65
60
5.5
7.0
8.5
10.0
11.5
13.0
14.5
16.0
Input Voltage, V_{IN} (V)
2 strings, 6 series LEDs each
2 strings, 7 series LEDs each
2 strings, 8 series LEDs each

Functional Description

Enabling the IC

The IC turns on when a logic high signal is applied on the PWM pin with a minimum duration of t_{PWMH} for the first clock cycle, and the input voltage present on the VIN pin is greater than the 4.35 V necessary to clear the UVLO ($V_{UVLOrise}$) threshold. The power-up sequence is shown in figure 2. Before the LEDs are enabled, the A8515 driver goes through a system check to determine if there are any possible fault conditions that might prevent the system from functioning correctly. Also if the FSET pin is pulled low, the IC will not power-up. More information on the FSET pin can be found in the Sync section of this datasheet.

Powering up: LED pin short-to-GND check

The VIN pin has a UVLO function that prevents the A8515 from powering-up until the UVLO threshold is reached. After the VIN pin goes above UVLO, and a high signal is present on the PWM pin, the IC proceeds to power-up. As shown in figure 3, at this point the A8515 enables the disconnect switch and checks if any LED pins are shorted to GND and/or are not used. If a LED pin is shorted to ground the A8515 will not proceed with soft start until the short is removed from the LED pin. This prevents the A8515 from powering-up and putting an uncontrolled amount of current through the LEDs. The various detect scenarios are presented on the next page, in figures 4A to 4C.

The LED detect phase starts when the GATE voltage of the disconnect switch is equal to V_{IN} – 4.5 V. After the voltage threshold on the LEDx pins exceeds 120 mV, a delay of between 3000 and 4000 clock cycles is used to determine the status of the pins. Thus the LED detection duration varies with the switching frequency, as shown in the following table:

Switching Frequency (MHz)	Detection Time (ms)
2	1.5 to 2
1	3 to 4
0.800	3.75 to 5
0.600	5 to 6.7

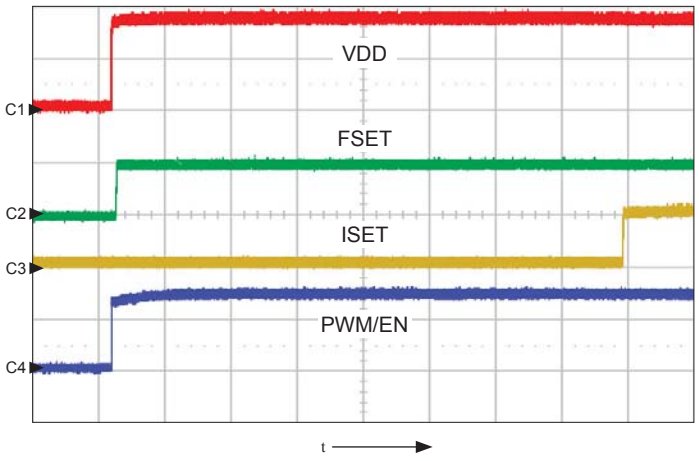


Figure 2. Power-up diagram; shows VDD (ch1, 2 V/div.), FSET (ch2, 1 V/div.), ISET (ch3, 1 V/div.), and PWM/EN (ch4, 2 V/div.) pins, 200 µs/div.

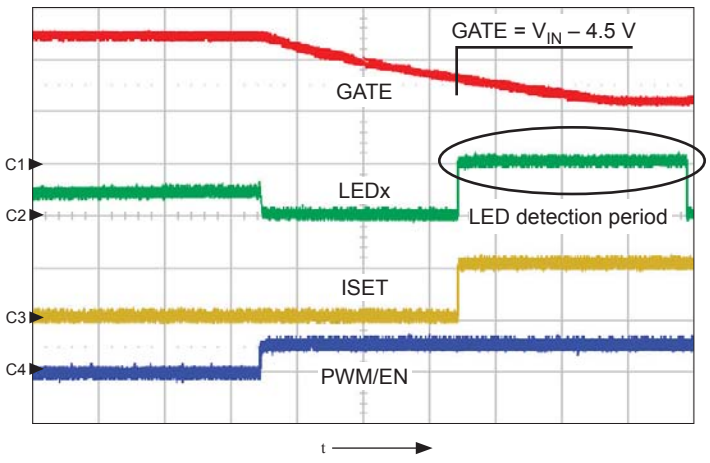


Figure 3. Power-up diagram; shows the relationship of an LEDx pin with respect to the gate voltage of the disconnect switch (if used) during the LED detect phase, as well as the duration of the LED detect phase for a switching frequency of 2 MHz; shows GATE (ch1, 5 V/div.), ILED (ch2, 500 mV/div.), ISET (ch3, 1 V/div.), and PWM/EN (ch4, 5 V/div.) pins, 500 µs/div.

The LED pin detection voltage thresholds are as follows:

LED Pin Voltage	LED Pin Status	Action
<170 mV	Short-to-GND	Power-up is halted
150 mV	Not used	LED removed from operation
325 mV	LED pin in use	None

All unused pins should be connected with a 1.54 kΩ resistor to GND, as shown in figure 5. The unused pin, with the pull-down resistor, will be taken out of regulation at this point and will not contribute to the boost regulation loop.

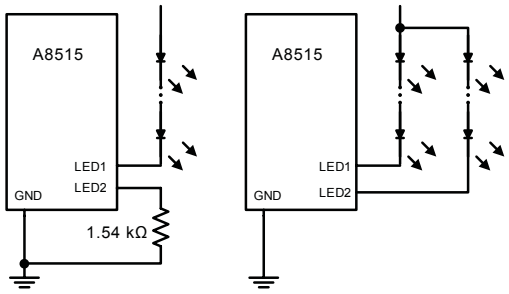
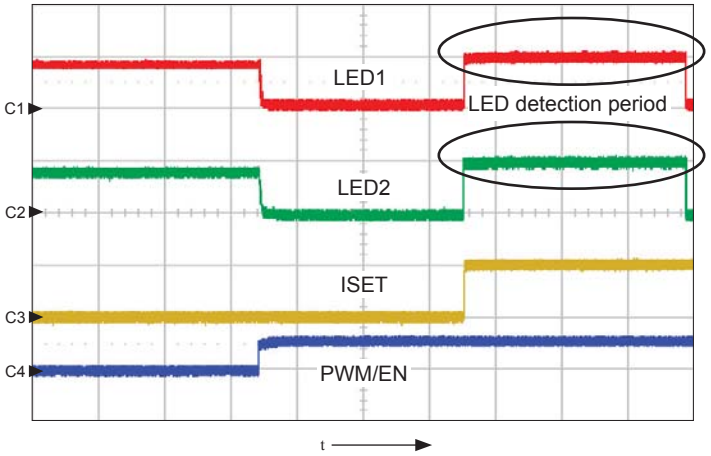
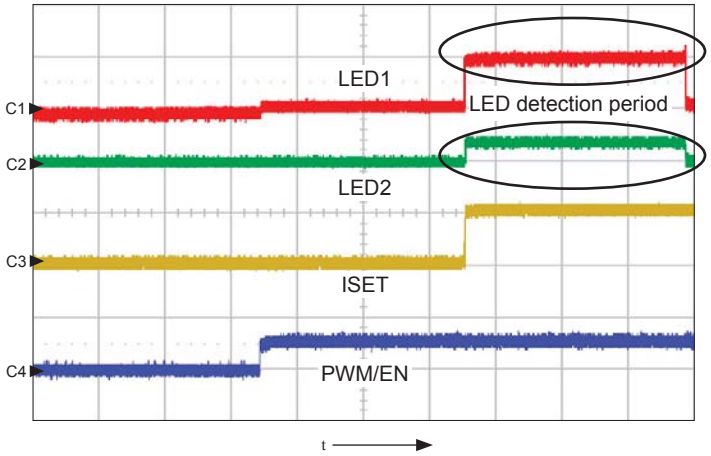


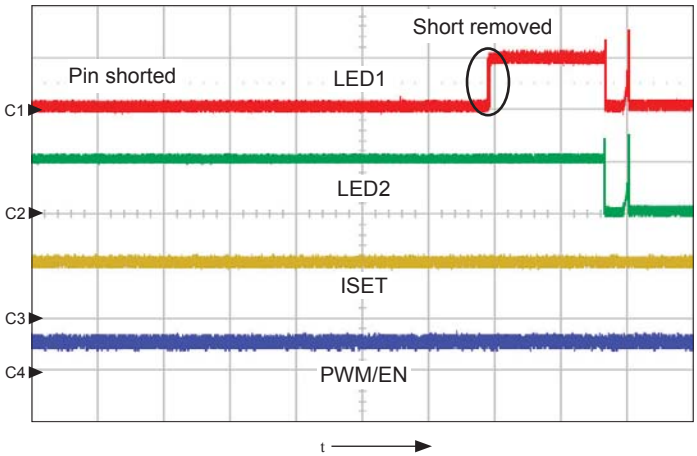
Figure 5. Channel select setup: (left) using only channel LED1, (right) using both channels.



4A. An LED detect occurring when both LED pins are selected to be used; shows LED1 (ch1, 500 mV/div.), LED2 (ch2, 500 mV/div.), ISET (ch3, 1 V/div.), and PWM/EN (ch4, 5 V/div.) pins, 500 µs/div.



4B. Example with LED2 pin not being used; the detect voltage is about 150 mV; shows LED1 (ch1, 500 mV/div.), LED2 (ch2, 500 mV/div.), ISET (ch3, 1 V/div.), and PWM/EN (ch4, 5 V/div.) pins, 500 µs/div.



4C. Example with one LED shorted to GND. The IC will not proceed with power-up until the shorted LED pin is released, at which point the LED is checked to see if it is being used ; shows LED1 (ch1, 500 mV/div.), LED2 (ch2, 500 mV/div.), ISET (ch3, 1 V/div.), and PWM/EN (ch4, 5 V/div.) pins, 1 ms/div.

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Soft start function

During soft start the LEDx pins are set to sink (I_{LEDSS}) and the boost switch current is reduced to the $I_{SWSS(LIM)}$ level to limit the inrush current generated by charging the output capacitors. When the converter senses that there is enough voltage on the LED pins the converter proceeds to increase the LED current to the preset regulation current and the boost switch current limit is switched to the $I_{SW(LIM)}$ level to allow the A8515 to deliver the necessary output power to the LEDs. This is shown in figure 7.

Frequency selection

The switching frequency on the boost regulator is set by the resistor connected to the FSET pin, and the switching frequency can be can be anywhere from 600 kHz to 2.0 MHz. Figure 6 shows the typical switching frequencies, in MHz, for given resistor values, in kΩ.

If during operation a fault occurs that will increase the switching frequency, the FSET pin is clamped to a maximum switching frequency of no more than 3.5 MHz. If the FSET pin is shorted to GND the part will shut down. For more details see the Fault Mode table later in this section.

Sync

The A8515 can also be synchronized using an external clock on the SYNC pin. Figure 8 shows the correspondence of a sync signal and the FSET pin, and figure 9 shows the result when a sync signal is detected: the LED current does not show any variation while the frequency changeover occurs. At power-up if the FSET pin is held low, the IC will not power-up. Only when the FSET pin is tri-stated to allow for the pin to rise, to about 1 V, or when a sync clock is detected, will the A8515 try to power-up.

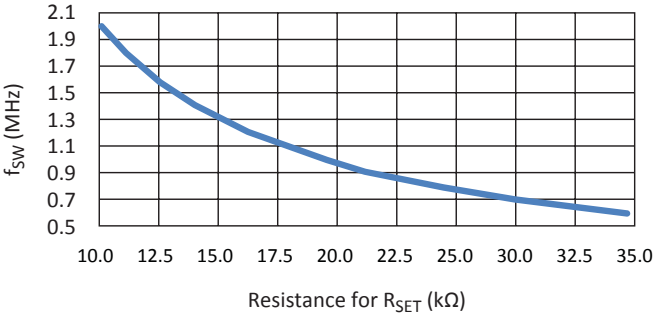


Figure 6. Typical Switching Frequency versus value of R_{FSET} resistor.

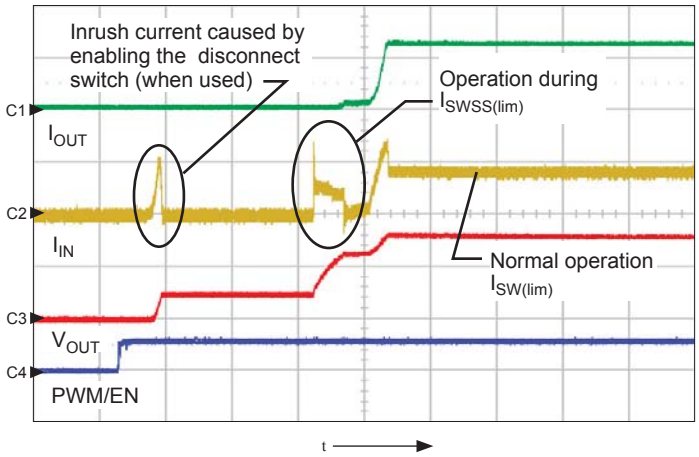


Figure 7. Startup diagram showing the input current, output voltage, and output current; shows I_{OUT} (ch1, 200 mA/div.), I_{IN} (ch2, 1 A/div.), V_{OUT} (ch3, 20 V/div.), and PWM/EN (ch4, 5 V/div.), 1 ms/div.

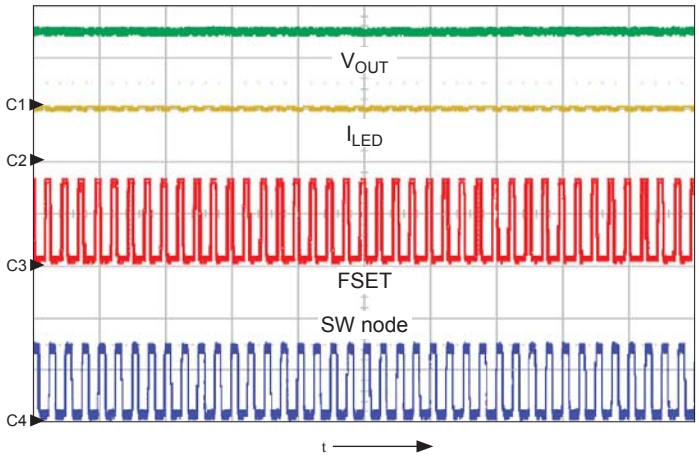


Figure 8. Diagram showing a synchronized FSET pin and switch node; shows V_{OUT} (ch1, 20 V/div.), I_{LED} (ch2, 200 mA/div.), FSET (ch3, 2 V/div.), and SW node (ch4, 20 V/div.), 2 µs/div.

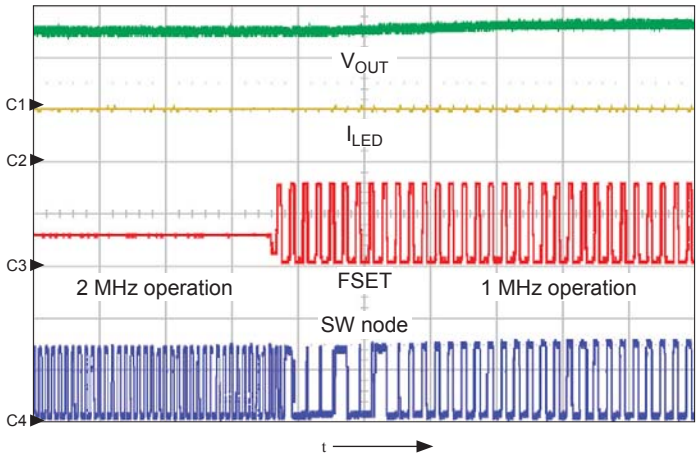


Figure 9. Transition of the SW waveform when the SYNC pulse is detected. The A8515 switching at 2 MHz, applied SYNC pulse at 1 MHz; shows V_{OUT} (ch1, 20 V/div.), I_{LED} (ch2, 200 mA/div.), FSET (ch3, 2 V/div.), and SW node (ch4, 20 V/div.), 5 µs/div.

The basic requirement of the sync signal is 150 ns minimum on-time and 150 ns minimum off time, as indicated by the specifications for $t_{PWSYNCON}$ and $t_{PWSYNCOFF}$. Figure 9 shows the timing for a synchronization clock into the A8515 at 2.2 MHz. Thus any pulse with a duty cycle of 33% to 66% at 2.2 MHz can be used to synchronize the IC. The rise and fall edges should be about 10 ns.

The SYNC pulse duty cycle ranges for selected switching frequencies are:

SYNC Pulse Frequency (MHz)	Duty Cycle Range (%)
2.2	33 to 66
2	30 to 70
1	15 to 85
0.800	12 to 88
0.600	9 to 91

If during operation a sync clock is lost, the IC will revert to the preset switching frequency that is set by the resistor R_{FSET}. During this period the IC will stop switching for a maximum period of about 7 µs to allow the sync detection circuitry to switch over to the externally preset switching frequency. If the clock is held low for more than 7 µs, the A8515 will shut down. In this shutdown mode the IC will stop switching, the input disconnect switch is open, and the LEDs will stop sinking current. To shutdown the IC into low power mode, the user needs to disable the IC using the PWM pin, by keeping the pin low for a period of 65 ms. If the FSET pin is released at any time after 5 µs, the A8515 will proceed to soft start.

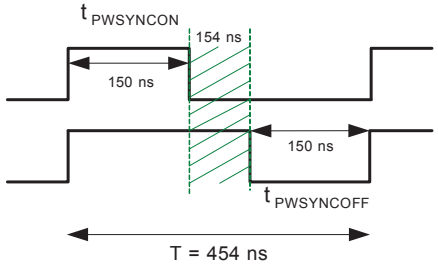


Figure 9. SYNC pulse on and off time requirements.

LED current setting and LED dimming

The maximum LED current can be up to 120 mA per channel, and is set through the ISET pin. To set the ILED current, connect a resistor, R_{ISET}, between this pin and GND, according to the following formula:

$$R_{ISET} = 980 / I_{LED} \quad (1)$$

where I_{LED} is in A and R_{ISET} is in Ω. This sets the maximum current through the LEDs, referred to as the *100% current*. Standard R_{ISET} values, at gain equals 980, are as follows:

Standard Closest R_{ISET} Resistor Value (kΩ)	LED current per LED, I_{LED} (mA)
8.25	120
9.76	100
12.1	80
15.0	65

PWM dimming

The LED current can be reduced from the 100% current level by PWM dimming using the PWM pin. When the PWM pin is pulled high, the A8515 turns on and all enabled LEDs sink 100% current. When PWM is pulled low, the boost converter and LED sinks are turned off. The compensation (COMP) pin is floated, and critical internal circuits are kept active. The typical PWM dimming frequencies fall between 200 Hz and 1 kHz. Figures 11A to 11D provide examples of PWM switching behavior.

Another important feature of the A8515 is the PWM signal to LED current delay. This delay is typically less than 500 ns, which allows greater accuracy at low PWM dimming duty cycles, as shown in figure 10.

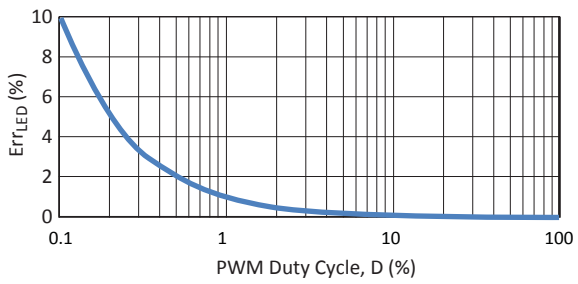


Figure 10. Percentage Error of the LED current versus PWM duty cycle.

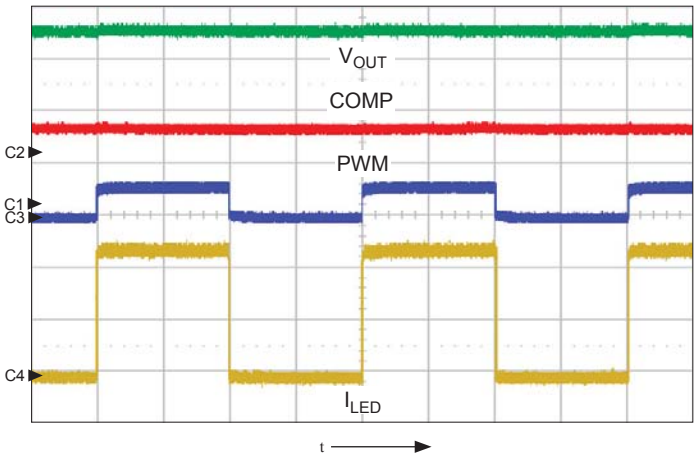


Figure 11A. Typical PWM diagram showing V_{OUT}, I_{LED}, and COMP pin as well as the PWM signal. PWM dimming frequency is 500 Hz at 50% duty cycle; shows V_{OUT} (ch1, 10 V/div.), COMP (ch2, 2 V/div.), PWM (ch3, 5 V/div.), and I_{LED} (ch4, 100 mA/div.), 500 µs/div.

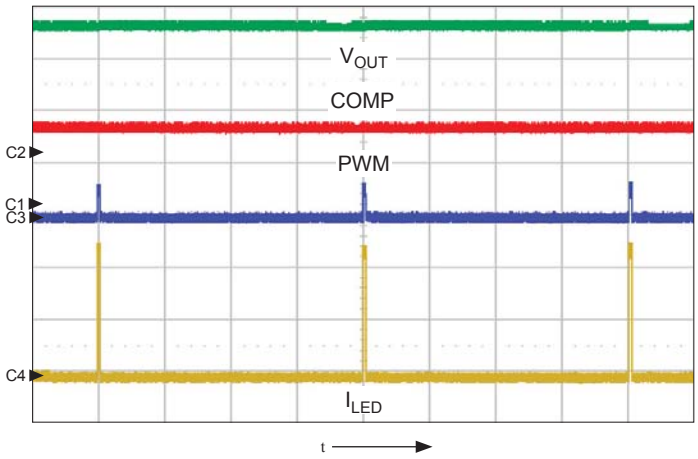


Figure 11B. Typical PWM diagram showing V_{OUT}, I_{LED}, and COMP pin as well as the PWM signal. PWM dimming frequency is 500 Hz at 1% duty cycle ; shows V_{OUT} (ch1, 10 V/div.), COMP (ch2, 2 V/div.), PWM (ch3, 5 V/div.), and I_{LED} (ch4, 100 mA/div.), 500 µs/div.

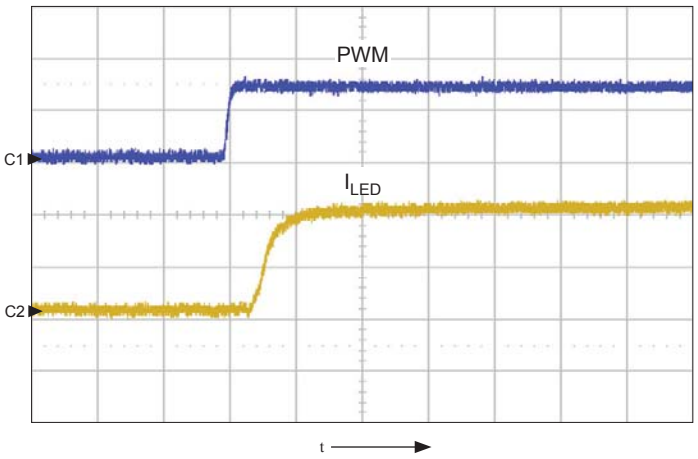


Figure 11C. Delay from rising edge of PWM signal to LED current; shows PWM (ch1, 2 V/div.), and I_{LED} (ch2, 50 mA/div.), 200 ns/div.

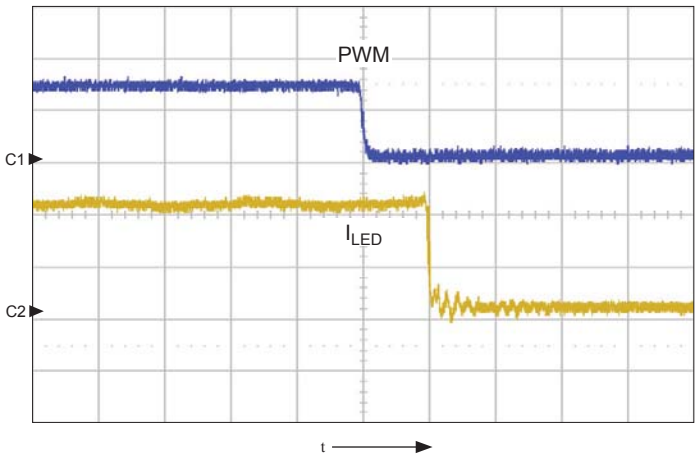


Figure 11D. Delay from falling edge of PWM signal to LED current turn off; shows PWM (ch1, 2 V/div.), and I_{LED} (ch2, 50 mA/div.), 200 ns/div.

APWM pin

The APWM pin is used in conjunction with the ISET pin. This is a digital signal pin that internally adjusts the ISET current. The typical input signal frequency is between 20 kHz and 1 MHz. The duty cycle of this signal is inversely proportional to the percentage of current that is delivered to the LEDs (figure 13). As an example: a system that delivers a full LED current of 120 mA per LED would deliver 90 mA of current per LED when an APWM signal is applied with a duty cycle of 25%. When this pin is not used it should be tied to GND.

To use this pin for a trim function, the user should set the maximum output current to a value higher than the required current by at least 5%. The LED ISET current is then trimmed down to the

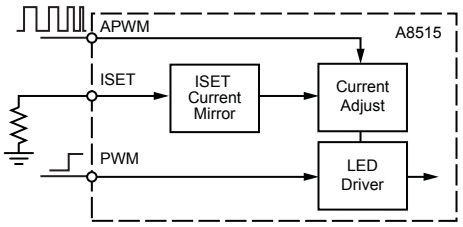


Figure 12. Simplified block diagram of the APWM ISET block.

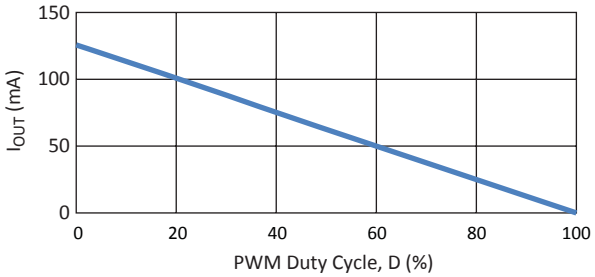


Figure 13. Output current versus duty cycle; 200 kHz APWM signal.

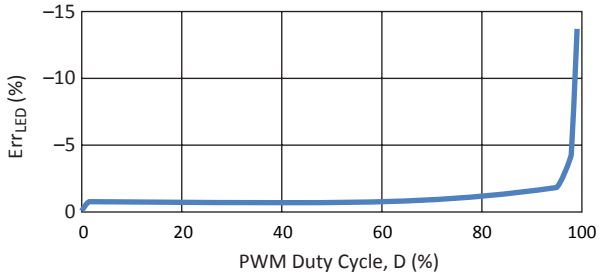


Figure 14. Percentage Error of the LED current versus PWM duty cycle; 200 kHz APWM signal.

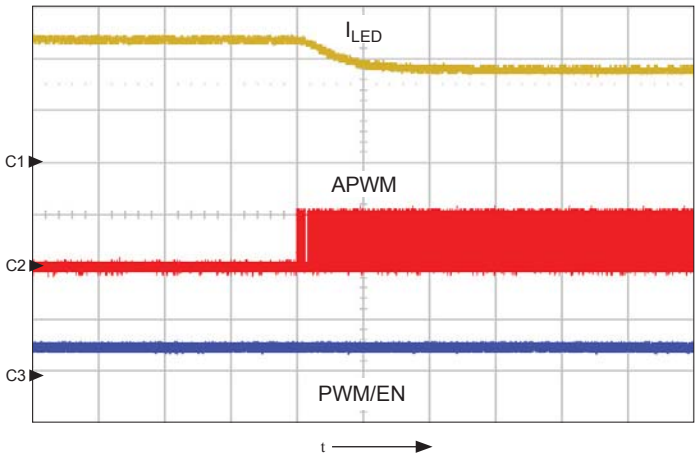


Figure 15. Diagram showing the transition of LED current from 120 mA to 90 mA, when a 25% duty cycle signal is applied to the APWM pin; PWM = 1; shows I_{LED} (ch1, 50 mA/div.), APWM (ch2, 5 V/div.), and PWM/EN (ch3, 5 V/div.), 500 µs/div.

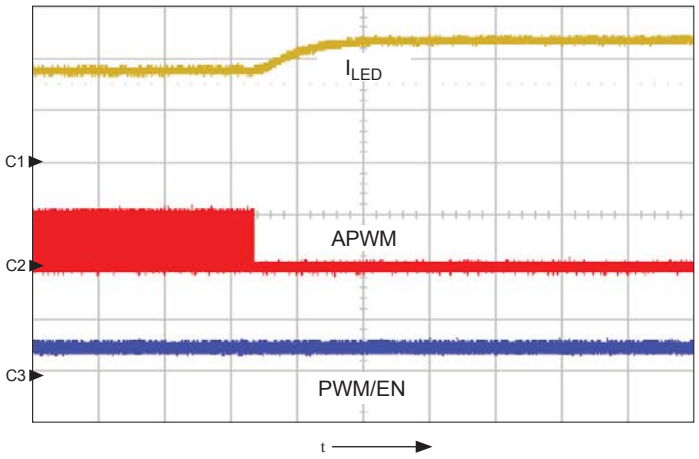


Figure 16. Diagram showing the transition of LED current from 90 mA to 120 mA, when a 25% duty cycle signal is removed from the APWM pin. PWM = 1; shows I_{LED} (ch1, 50 mA/div.), APWM (ch2, 5 V/div.), and PWM/EN (ch3, 5 V/div.), 500 µs/div.

appropriate value. Another consideration that also is important is the limitation of the user APWM signal duty cycle. In some cases it might be preferable to set the maximum ISET current to be 25% to 50% higher, thus allowing the APWM signal to have duty cycles that are between 25% and 50%.

Although the APWM dimming function has a wide frequency range, if this function is used strictly as an analog dimming function it is recommended to use frequency ranges between 50 and 500 kHz for best accuracy. The frequency range must be considered only if the user is not using this function as a closed loop trim function. Another limitation is that the propagation delay between this APWM signal and I_{OUT} takes several milliseconds to change the actual LED current. This effect is shown in figure 17.

LED short detect

Both LEDx pins are capable of handling the maximum V_{OUT} that the converter can deliver, thus providing protection from the LED pin to V_{OUT} in the event of a connector short.

An LED pin that has a voltage exceeding V_{LEDSC} will be removed from operation (see figure 18). This is to prevent the IC from dissipating too much power by having a large voltage present on an LEDx pin.

While the IC is being PWM-dimmed, the IC rechecks the disabled LED every time the PWM signal goes high, to prevent false tripping of an LED short event. This also allows some self-correction if an intermittent LED pin short-to-V_{OUT} is present.

Overvoltage protection

The A8515 has overvoltage protection (OVP) and open Schottky diode protection. The OVP protection has a default level of 8 V and can be increased up to 55 V by connecting R_{OVP} between the OVP pin and V_{OUT}. When the current into the OVP pin exceeds 200 µA typical, the OVP comparator goes low and the boost stops switching.

The following equation can be used to determine the resistance for setting the OVP level:

$$R_{OVP} = (V_{OUTovp} - V_{OVP(th)}) / I_{OVPH} \quad (2)$$

where:

V_{OUTovp} is the target overvoltage level,

R_{OVP} is the value of the external resistor, in Ω,

$V_{OVP(th)}$ is the pin OVP trip point found in the Electrical Characteristics table, and

I_{OVPH} is the current into the OVP pin.

There are several possibilities for why an OVP condition would be encountered during operation, the two most common being: a disconnected output, and an open LED string. Examples of these are provided in figures 19 and 20.

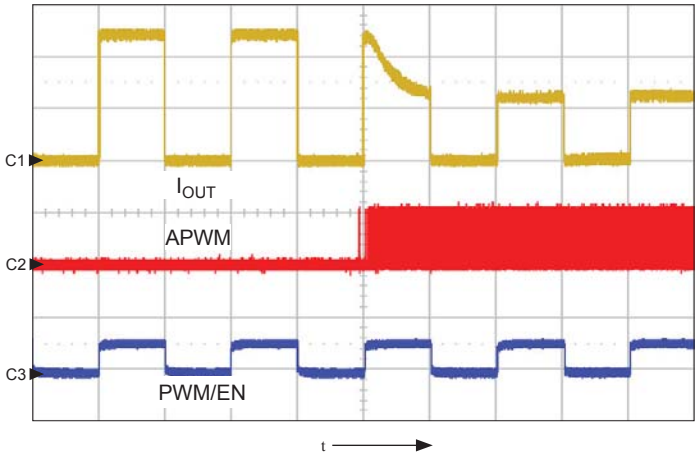


Figure 17. Transition of output current level when a 50% duty cycle signal is applied to the APWM pin, in conjunction with a 50% duty cycle PWM dimming being applied to the PWM pin; shows I_{OUT} (ch1, 100 mA/div.), APWM (ch2, 5 V/div.), and PWM/EN (ch3, 5 V/div.), 1 ms/div.

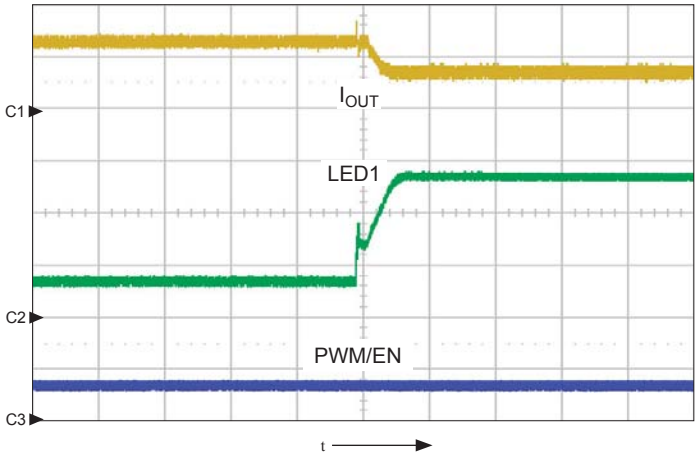


Figure 18. Example of the disabling of an LED string when the LED pin voltage is increased above 4.6 V; shows I_{OUT} (ch1, 200 mA/div.), LED1 (ch2, 5 V/div.), and PWM/EN (ch3, 5 V/div.), 10 µs/div.

Figure 19 illustrates when the output of the A8515 is disconnected from load during normal operation. The output voltage instantly increases up to OVP voltage level and then the boost stops switching to prevent damage to the IC. If the output is drained off, eventually the boost might start switching for a short duration until the OVP threshold is hit again.

Figure 20 displays a typical OVP event caused by an open LED string. After the OVP condition is detected, the boost stops switching, and the open LED string is removed from operation. Afterwards V_{OUT} is allowed to fall, and eventually the boost will resume switching and the A8515 will resume normal operation.

A8515 also has built-in secondary overvoltage protection to protect the internal switch in the event of an open diode condition. Open Schottky diode detection is implemented by detecting overvoltage on the SW pin of the device. If voltage on the SW pin exceeds the device safe operating voltage rating, the A8515 disables and remains latched. To clear this fault, the IC must be shut down either by using the PWM signal or by going below the UVLO threshold on the VIN pin. Figure 21 illustrates this. As soon as the switch node voltage (SW) exceeds 60 V, the IC shuts down. Due to small delays in the detection circuit, as well as there being no load present, the switch node voltage will rise above the trip point voltage.

Figure 22 illustrates when the A8515 is being enabled during an open diode condition. The IC goes through all of its initial LED detection and then tries to enable the boost, at which point the open diode is detected.

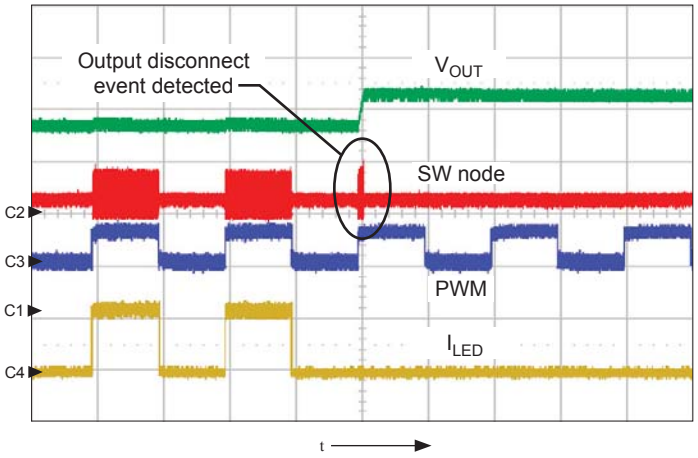


Figure 19. OVP protection in an output disconnect event; shows V_{OUT} (ch1, 10 V/div.), SW node (ch2, 50 V/div.), PWM (ch3, 5 V/div.), and I_{LED} (ch4, 200 mA/div.), 1 ms/div.

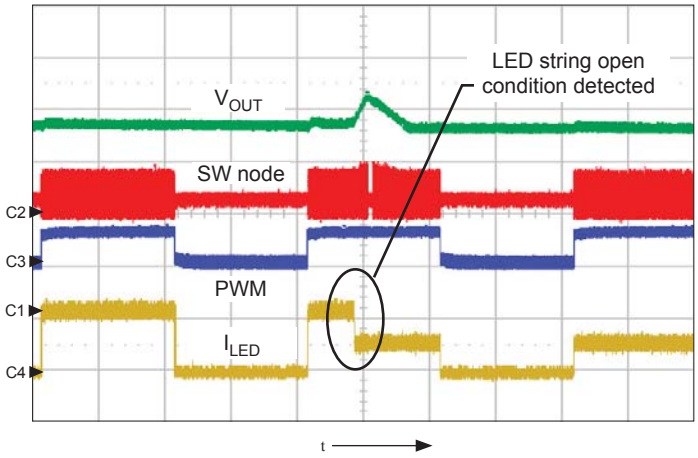


Figure 20. OVP protection in an open LED string event; shows V_{OUT} (ch1, 10 V/div.), SW node (ch2, 50 V/div.), PWM (ch3, 5 V/div.), and I_{LED} (ch4, 200 mA/div.), 500 µs/div.

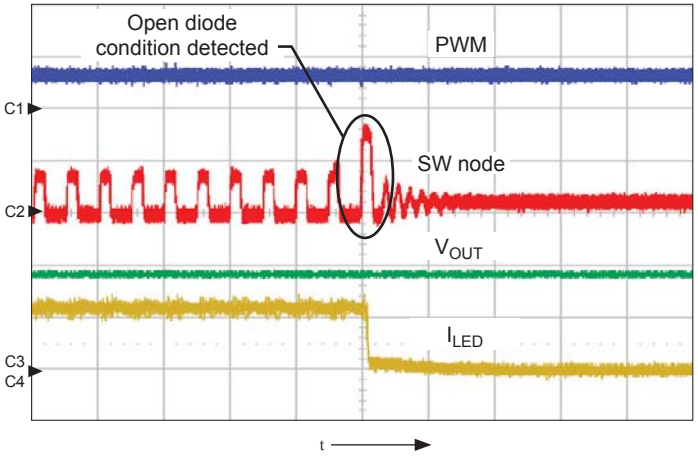


Figure 21. OVP protection in an open Schottky diode event, while the IC is in normal operation; shows PWM (ch1, 5 V/div.), SW node (ch2, 50 V/div.), V_{OUT} (ch3, 20 V/div.), and I_{LED} (ch4, 200 mA/div.), 1 µs/div.

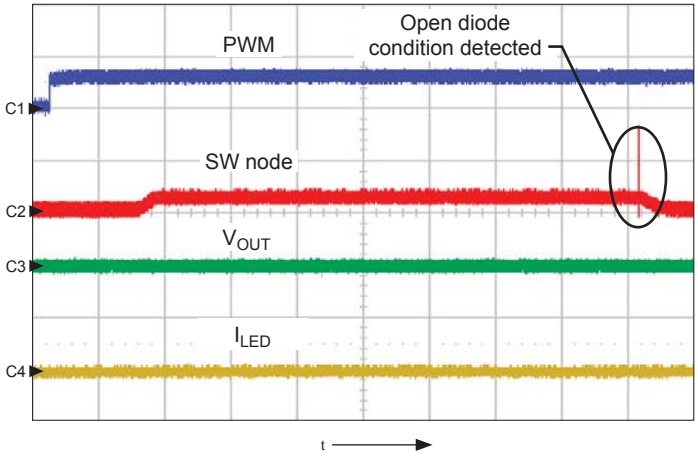


Figure 22. OVP protection when the IC is enabled during an open diode condition; shows PWM (ch1, 5 V/div.), SW node (ch2, 50 V/div.), V_{OUT} (ch3, 10 V/div.), and I_{LED} (ch4, 200 mA/div.), 500 µs/div.

Boost switch overcurrent protection

The boost switch is protected with pulse-by-pulse current limiting set at a minimum of 3.0 A. There is also a secondary current limit that is sensed on the boost switch. When detected this current limit immediately shuts down the A8515. The level of this current limit is set above the pulse-by-pulse current limit to protect the switch from destructive currents when the boost inductor is shorted.

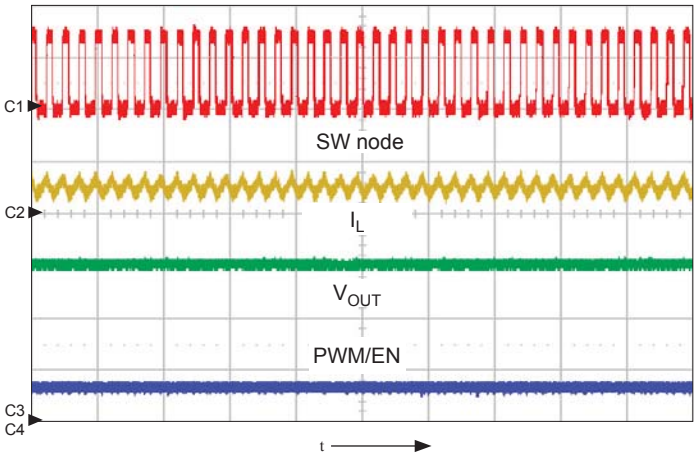


Figure 23. Normal operation of the switch node (SW); inductor current (I_L) and output voltage (V_{OUT}) for 9 series LEDs in each of 2 strings configuration; shows SW node (ch1, 20 V/div.), I_L (ch2, 1 A/div.), V_{OUT} (ch3, 10 V/div.), and PWM/EN (ch4, 5 V/div.), 2 µs/div.

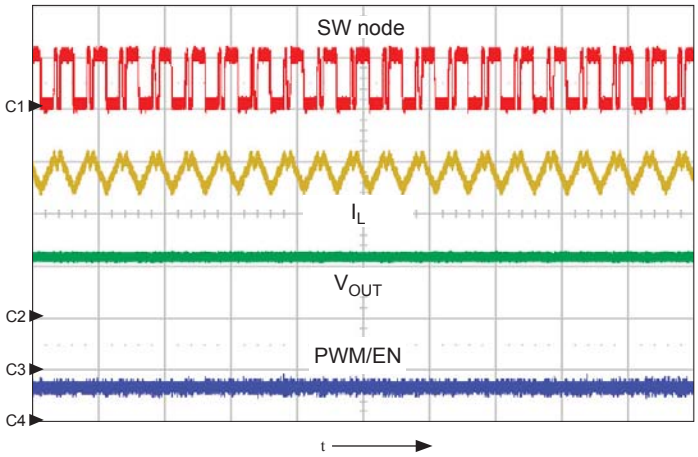


Figure 24. Pulse-by-pulse current limiting; inductor current (yellow trace, I_L), note reduction in output voltage as compared to normal operation with the same configuration (figure 23); shows SW node (ch1, 20 V/div.), I_L (ch2, 1 A/div.), V_{OUT} (ch3, 10 V/div.), and PWM/EN (ch4, 5 V/div.), 2 µs/div.

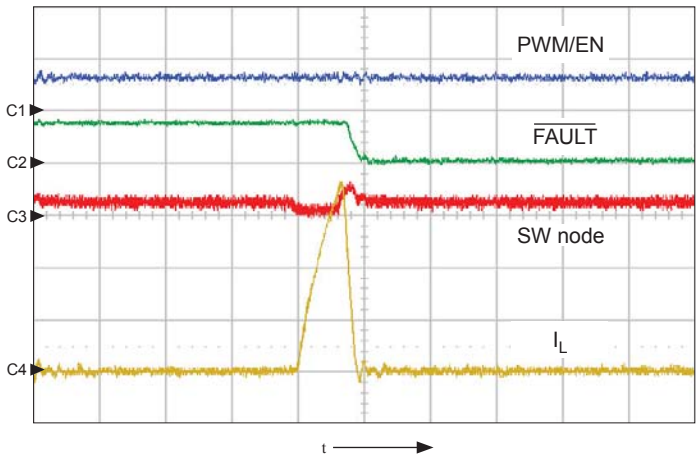


Figure 25. Secondary boost switch current limit; when this limit is hit, the A8515 immediately shuts down; shows PWM (ch1, 5 V/div.), V_{OUT} (ch2, 5 V/div.), SW node (ch3, 50 V/div.), and I_L (ch4, 2 A/div.), 100 ns/div.

Input overcurrent protection and disconnect switch

The primary function of the input disconnect switch is to protect the system and the device from catastrophic input currents during a fault condition. The external circuit implementing the disconnect is shown in figure 26.

The input disconnect switch has two modes of operation:

• **Fault flag warning** When the input current is between 1 and 2 times the preset current limit (called the *1X current limit*) the A8515 sets the Fault flag ($\overline{\text{FAULT}}$ set low), but continues to operate normally. If the current decreases below the 1X current limit, then the flag will reset.

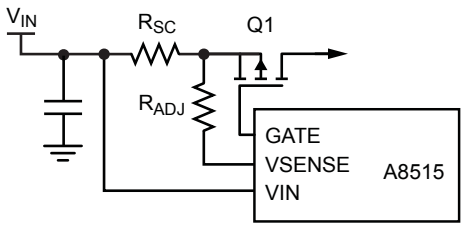


Figure 26. Typical circuit showing the implementation of the input disconnect feature.

• **2X current limit** If the input current level goes above 2X of the preset current limit threshold, the A8515 will shut down in less than 2 µs regardless of user input. This is a latched condition. The Fault flag is also set to indicate a fault. This feature is meant to prevent catastrophic failure in the system due to a short of the inductor to GND (see figure 28).

Setting the current sense resistor

The typical threshold for the current sense circuit is 98 mV, when R_{ADJ} is 0 Ω. This voltage can be trimmed by the R_{ADJ} resistor. The typical 1X trip point should be set at about 3 A, which coincides with the pulse-by-pulse current limit minimum threshold. A sample calculation is done below:

Given: 3 A of input current, and the calculated maximum value of the sense resistor, R_{SC} = 0.033 Ω.

The R_{SC} chosen is 0.03 Ω, a standard.

Also:

$$R_{ADJ} = (V_{SENSETRIP} - V_{ADJ}) / I_{ADJ} \quad (3)$$

The trip point voltage is calculated as:

$$V_{ADJ} = 3.0\ \text{A} \times 0.03\ \Omega = 0.090\ \text{V}$$

$$R_{ADJ} = (0.098 - 0.09\ \text{V}) / (20.5\ \mu\text{A}) = 390\ \Omega$$

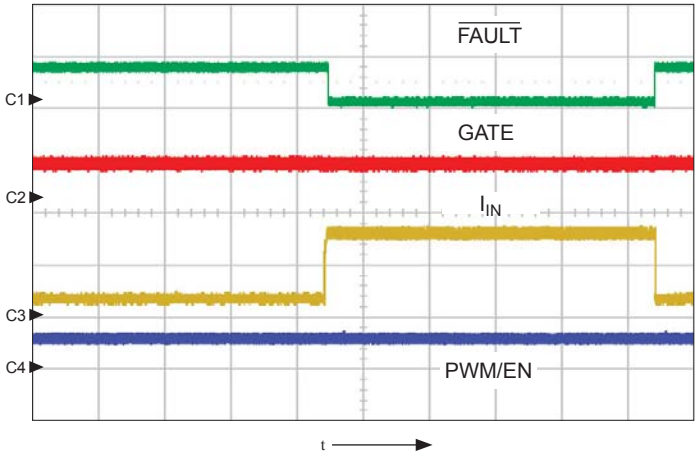


Figure 27. Setting of the Fault flag for excessive input (I_{IN}) currents, and then resetting the flag when the input current goes below the 1X current trip point; shows $\overline{\text{FAULT}}$ (ch1, 5 V/div.), GATE (ch2, 10 V/div.), I_{IN} (ch3, 2 A/div.), and PWM/EN (ch4, 5 V/div.), 10 ms/div.

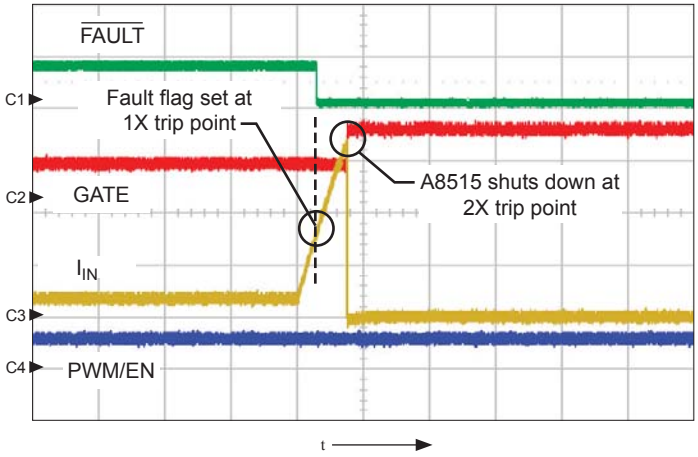


Figure 28. Typical secondary overcurrent fault condition. I_{IN} is the input current through the switch. The Fault flag is set at the 1X current limit, and when the 2X current limit is reached the A8515 disables the gate of the disconnect switch (GATE); shows $\overline{\text{FAULT}}$ (ch1, 5 V/div.), GATE (ch2, 10 V/div.), I_{IN} (ch3, 2 A/div.), and PWM/EN (ch4, 5 V/div.), 5 ms/div..

Input UVLO

When V_{IN} and V_{SENSE} rise above the $V_{UVLOrise}$ threshold, the A8515 is enabled. A8515 is disabled when V_{IN} falls below the $t_{UVLOfall}$ threshold for more than 50 µs. This small delay is used to avoid shutting down because of momentary glitches in the input power supply. When V_{IN} falls below 4.35 V, the IC will shut down (see figure 29).

VDD

The VDD pin provides regulated bias supply for internal circuits. Connect the capacitor C_{VDD} with a value of 0.1 µF or greater to this pin. The internal LDO can deliver no more than 2 mA of current with a typical V_{DD} of about 3.5 V, enabling this pin to serve as the pull-up voltage for the $\overline{FAULT}$ pin.

Shutdown

If the PWM pin is pulled low for more than t_{PWML}, the device enters shutdown mode and clears all internal fault registers. As an example, at a 2 MHz clock frequency, it will take approximately 16.3 ms to shut down the IC into the low power mode (figure 30). When the A8515 is shut down, the IC will disable all current sources and wait until the PWM goes high to re-enable the IC. If faster shut down is required the FSET pin can be used.

Fault protection during operation

The A8515 constantly monitors the state of the system to determine if any fault conditions occur during normal operation. The response to a triggered fault condition is summarized in the Fault Mode table, on the next page.

It is important to note that there are several points at which the A8515 monitors for faults during operation. The locations are: input current, switch current, and output voltage switch voltage and the two LEDx pins. Note: some of the protection features might not be active during startup, to prevent false triggering of fault conditions.

The possible fault conditions that the device can detect are: Open LED pin, LED pin shorted to GND, shorted inductor, V_{OUT} short to GND, SW pin shorted to GND, ISET pin shorted to GND, and input disconnect switch source shorted to GND.

Note: Some of these faults will not be protected if the input disconnect switch is not being used. An example of this is V_{OUT} short to GND.

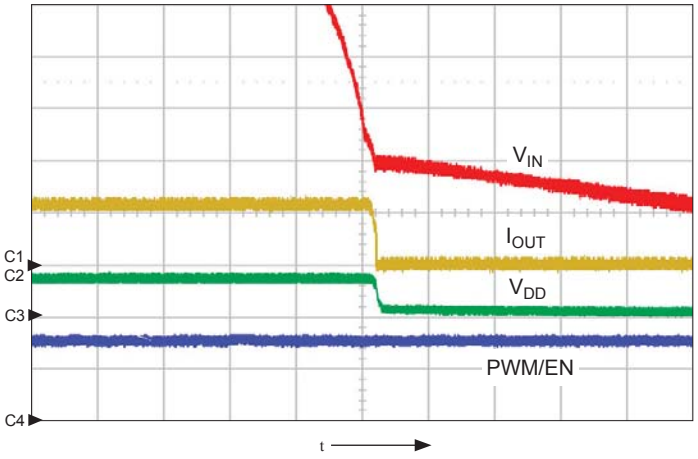


Figure 29. Shutdown showing a falling input voltage (V_{IN}); shows V_{IN} (ch1, 2 V/div.), I_{OUT} (ch2, 200 mA/div.), V_{DD} (ch3, 5 V/div.), and PWM/EN (ch4, 2 V/div.), 5 ms/div.

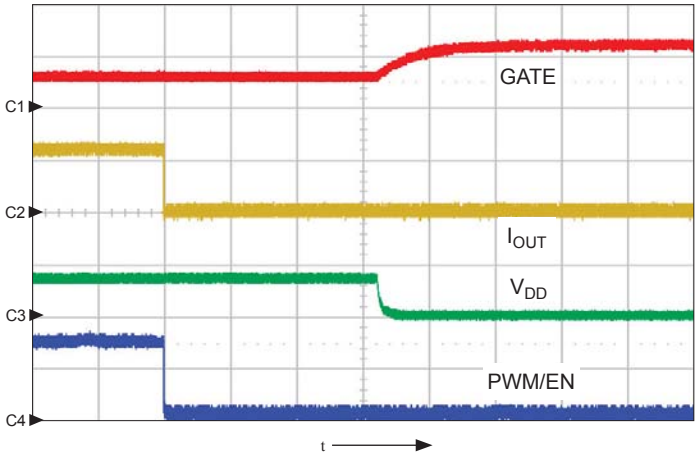


Figure 30. Shutdown using the enable function, showing the 16 ms delay between the PWM/EN signal and when the VDD and GATE of the disconnect switch turns off; shows GATE (ch1, 10 V/div.), I_{OUT} (ch2, 200 mA/div.), V_{DD} (ch3, 5 V/div.), and PWM/EN (ch4, 2 V/div.), 5 ms/div.

Fault Mode Table

Fault Name	Type	Active	Fault Flag Set	Description	Boost	Disconnect switch	Sink driver
Primary switch overcurrent protection (pulse-by-pulse current limit)	Auto-restart	Always	No	This fault condition is triggered by the pulse-by-pulse current limit, $I_{SW(LIM)}$. Prevents current in inductor from exceeding $I_{SW(LIM)}$ 3.38 A (Typical).	Off for a single cycle	On	On
Secondary switch current limit	Latched	Always	Yes	When the current through the boost switch exceeds secondary current SW limit ($I_{SW(LIM2)}$) the device immediately shuts down the disconnect switch, LED drivers, and boost. The Fault flag is set. To re-enable the device, the PWM pin must be pulled low for 32750 clock cycles.	Off	Off	Off
Input disconnect current limit	Latched	Always	Yes	The device is immediately shut off if the voltage across the input sense resistor is 2X the preset current value. The Fault flag is set. If the input current limit is between 1X and 2X, the Fault flag is set but the IC will continue to operate normally until it is shut down. If the input current goes below the 1X threshold, the Fault flag will reset. To re-enable the device the PWM pin must to be pulled low for 32750 clock cycles.	Off	Off	Off
Secondary OVP	Latched	Always	Yes	Secondary overvoltage protection is used for open diode detection. When diode D1 opens, the SW pin voltage will increase until $V_{OVP(SEC)}$ is reached. This fault latches the IC. The input disconnect switch is disabled as well as the LED drivers, and the Fault flag is set. To re-enable the part the PWM pin must be pulled low for 32750 clock cycles.	Off	Off	Off
LED Pin Short Protection	Auto-restart	Startup	No	This fault prevents the device from starting-up if any of the LEDx pins are shorted. The device stops soft-start from starting while any of the LED pins are determined to be shorted. Once the short is removed, soft-start is allowed to start.	Off	On	Off
LED Pin open	Auto-restart	Normal Operation	No	When an LED pin is open the device will determine which LED pin is open by increasing the output voltage until OVP is reached. Any LED string not in regulation will be turned off. The device will then go back to normal operation by reducing the output voltage to the appropriate voltage level.	On	On	Off for open pins. On for all others.
ISET Short Protection	Auto-restart	Always	No	This fault occurs when the ISET current goes above 150% of the maximum current. The boost will stop switching and the IC will disable the LED sinks until the fault is removed. When the fault is removed the IC will try to regulate to the preset LED current.	Off	On	Off

Continued on the next page…

Fault Mode Table (continued)

Fault Name	Type	Active	Fault Flag Set	Description	Boost	Disconnect Switch	Sink driver
FSET Short Protection	Auto-restart	Always	Yes	Fault occurs when the FSET current goes above 150% of maximum current. The boost will stop switching, the disconnect switch will turn off and the IC will disable the LED sinks until the fault is removed. When the fault is removed the IC will try to restart with soft-start.	Off	Off	Off
Overvoltage Protection	Auto-restart	Always	No	Fault occurs when OVP pin exceeds $V_{OVP(th)}$ threshold. The A8515 will immediately stop switching to try to reduce the output voltage. If the output voltage decreases then the A8515 will restart switching to regulate the output voltage.	Stop during OVP event.	On	On
IED Short Protection	Auto-restart	Always	No	Fault occurs when the LED pin voltage exceeds 5.1 V. When the LED short protection is detected the LED string above the threshold will be removed from operation.	On	On	Off for shorted pins. On for all others.
Overtemperature Protection	Auto-restart	Always	No	Fault occurs when the die temperature exceeds the overtemperature threshold, typically 165°C.	Off	Off	Off
VIN UVLO	Auto-restart	Always	No	Fault occurs when V_{IN} drops below V_{UVLO}, typically 4.35 V. This fault resets all latched faults.	Off	Off	Off

Applications Information

Design Example

This section provides a method for selecting component values when designing an application using the A8515. The resulting design is diagramed in figure 30.

Assumptions: For the purposes of this example, the following are given as the application requirements:

- V_{BAT}: 10 to 14 V
- Quantity of LED channels, $\#_{CHANNELS}$: 2
- Quantity of series LEDs per channel, $\#_{SERIESLEDS}$: 10
- LED current per channel, I_{LED}: 120 mA
- V_f at 65 mA: 3 to 3.6 V
- f_{SW}: 2 MHz
- T_A(max): 65°C
- PWM dimming frequency: 500 Hz, 1% Duty cycle

Procedure: The procedure consists of selecting the appropriate configuration and then the individual component values, in an ordered sequence.

Step 1 Connect LEDs to pins LED1 and LED2.

Step 2 Determining the LED current setting resistor R_{ISET}:

$$R_{ISET} = 999 / I_{LED} \quad (4)$$
$$= 999 / 120\ \text{mA} = 8.33\ \text{k}\Omega$$

Choose a 8.25 kΩ resistor.

Step 3 Determining the OVP resistor. The OVP resistor is connected between the OVP pin and the output voltage of the converter.

Step 3a The first step is determining the maximum voltage based on the LED requirements. Then this value and the regulation voltage (V_{LED}) should be added together, as well as another 600 mV to take noise and output ripple into consideration. The V_{LED} of the A8515 is 750 mV.

$$V_{OUT(OVP)} = \#_{SERIESLEDS} \times V_f + V_{LED} + 0.6 \quad (5)$$
$$= 10 \times 3.6\ \text{V} + 0.650\ \text{V} + 0.6\ \text{V}$$
$$= 37.35\ \text{V}$$

Then the OVP resistor is:

$$R_{OVP} = (V_{OUT(OVP)} - V_{OVP(th)}) / I_{OVPH} \quad (6)$$
$$= (37.35\ \text{V} - 7.6\ \text{V}) / 190\ \mu\text{A} = 156.58\ \text{k}\Omega$$

where both I_{OVPH} and $V_{OVP(th)}$ are taken from the Electrical Characteristics table.

Chose a value of resistor that is higher value than the calculated R_{OVP}. In this case a value of 162 kΩ was selected. Below is the actual value of the minimum OVP trip level with the selected resistor:

$$V_{OUT(OVP)} = 162\ \text{k}\Omega \times 190\ \mu\text{A} + 7.6\ \text{V} = 38.38\ \text{V}$$

Step 3b At this point a quick check must be done to see if the conversion ratio is acceptable for the selected frequency.

$$D_{maxofboost} = 1 - t_{SWONTIME} \times f_{SW} \quad (7)$$
$$= 1 - 85\ \text{ns} \times 2.2\ \text{MHz} = 81.3\%$$

where minimum on time ($t_{SWONTIME}$) is found in the Electrical Characteristics table.

The Theoretical Maximum V_{OUT} is then calculated as:

$$V_{OUTthe}(\text{max}) = \frac{V_{IN}(\text{min}) \times \eta}{1 - D_{maxofboost}} + V_d \quad (8)$$

$$= \frac{10\ \text{V} \times 0.9}{1 - 0.813} + 0.4 = 48.52\ \text{V}$$

where η is efficiency and V_d is the diode forward voltage. A good approximation of efficiency η can be taken from the efficiency curves located in this datasheet. A value of 90% is a good starting approximation.

The Theoretical Maximum V_{OUT} value must be greater than the value $V_{OUT(OVP)}$. If this is not the case, the switching frequency of the boost converter must be reduced to meet the maximum duty cycle requirements.

Step 4 Selecting the inductor. The inductor must be chosen such that it can handle the necessary input current. In most applications, due to stringent EMI requirements, the system must operate in continuous conduction mode throughout the whole input voltage range.

Step 4a Determining the duty cycle, calculated as follows:

$$D(\text{max}) = 1 - \frac{V_{IN}(\text{min}) \times \eta}{V_{OUT(OVP)} + V_d} \quad (9)$$

$$= 1 - \frac{10\ \text{V} \times 0.9}{38.38 + 0.4} = 77\%$$

Step 4b Determining the maximum and minimum input current to the system. The minimum input current will dictate the inductor value. The maximum current rating will dictate the current rating of the inductor. First, the maximum input current, given:

$$I_{OUT} = \#_{CHANNELS} \times I_{LED} \quad (10)$$

$$= 2 \times 0.120\ \text{A} = 0.240\ \text{A}$$

then:

$$I_{IN}(\text{max}) = \frac{V_{OUT(OVP)} \times I_{OUT}}{V_{IN}(\text{min}) \times \eta} \quad (11)$$

$$= \frac{38.38 \times 240\ \text{mA}}{10\ \text{V} \times 0.9} = 1.023\ \text{A}$$

Next, calculate minimum input current, as follows:

$$I_{IN}(\text{min}) = \frac{V_{OUT(OVP)} \times I_{OUT}}{V_{IN}(\text{max}) \times \eta} \quad (12)$$

$$= \frac{38.38 \times 200\ \text{mA}}{14\ \text{V} \times 0.9} = 0.731\ \text{A}$$

Step 4c Determining the inductor value. To ensure that the inductor operates in continuous conduction mode, the value of the inductor must be set such that the ½ inductor ripple current is not greater than the average minimum input current. A first past assumes I_{ripple} to be 40% of the maximum inductor current:

$$\Delta I_L = I_{IN}(\text{max}) \times I_{ripple} \quad (13)$$

$$= 1.023 \times 0.4 = 0.409\ \text{A}$$

then:

$$L = \frac{V_{IN}(\text{min})}{\Delta I_L \times f_{SW}} \times D(\text{max}) \quad (14)$$

$$= \frac{10\ \text{V}}{0.409\ \text{A} \times 2\ \text{MHz}} \times 0.77 = 9.4\ \mu\text{H}$$

Step 4d Double-check to make sure the ½ current ripple is less than I_{IN}(min):

$$I_{IN}(\text{min}) > {}^1/_2\ \Delta I_L \quad (15)$$

$$0.0731\ \text{A} > 0.205\ \text{A}$$

A good inductor value to use would be 10 µH.

Step 4e Determining the inductor current rating. The inductor current rating must be greater than the I_{IN}(max) value plus the ripple current ΔI_L, calculated as follows:

$$I_L(\text{max}) = I_{IN}(\text{max}) + {}^1/_2\ \Delta I_L \quad (16)$$

$$= 1.023\ \text{A} + 0.409\ \text{A} / 2 = 1.23\ \text{A}$$

Step 5 Determining the resistor value for a particular switching frequency. Use the R_{FSET} values shown in figure 7. For example, a 10 kΩ resistor will result in a 2 MHz switching frequency.

Step 6 Choosing the proper switching diode. The switching diode must be chosen for three characteristics when it is used in LED lighting circuitry. The most obvious two are: current rating of the diode and reverse voltage rating.

The reverse voltage rating should be such that during operation condition, the voltage rating of the device is larger than the maximum output voltage. In this case it is $V_{OUT(OVP)}$.

The peak current through the diode is calculated as:

$$I_{dp} = I_{IN}(\text{max}) + {}^1/_2\ \Delta I_L \quad (17)$$

$$= 1.023\ \text{A} + 0.409\ \text{A} / 2 = 1.23\ \text{A}$$

The third major component in deciding the switching diode is the reverse current characteristic of the diode. This characteristic is especially important when PWM dimming is implemented. During PWM off-time the boost converter is not switching. This results in a slow bleeding off of the output voltage, due to leakage currents. I_R or reverse current can be a large contributor, especially at high temperatures. On the diode that was selected in this design, the current varies between 1 and 100 µA.

Step 7 Choosing the output capacitors. The output capacitors must be chosen such that they can provide filtering for both the boost converter and for the PWM dimming function. The biggest factors that contribute to the size of the output capacitor are: PWM dimming frequency, and PWM duty cycle. Another major contributor is leakage current (I_{LK}). This current is the combination of the OVP current sense as well as the reverse current of the switching diode. In this design the PWM dimming frequency is 100 Hz and the minimum duty cycle is 1%. Typically the voltage

variation on the output (V_{COUT}) during PWM dimming must be less than 250 mV, so that no audible hum can be heard. The capacitance can be calculated as follows:

$$C_{OUT} = I_{LK} \times \frac{1 - D(\min)}{f_{PWM(dimming)} \times V_{COUT}} \quad (18)$$

$$= 800\ \mu A \times \frac{1 - 0.01}{500\ Hz \times 0.250\ V} = 6.33\ \mu F$$

A capacitor larger than 6.33 µF should be selected due to degradation of capacitance at high voltages on the capacitor. Two ceramic 4.7 µF 50 V capacitors are a good choice to fulfill this requirement. Corresponding capacitors include:

Vendor	Value	Part number
Murata	4.7 µF 50 V	GRM32ER71H475KA88L
Murata	2.2 µF 50 V	GRM31CR71H225KA88L

The rms current through the capacitor is given by:

$$I_{COUT}\text{rms} = I_{OUT} \sqrt{\frac{D(\max) + \frac{\Delta I_L}{I_{IN}(\max) \times 12}}{1 - D(\max)}} \quad (19)$$

$$= 0.180\ A \sqrt{\frac{0.77 + \frac{0.409}{1.023 \times 12}}{1 - 0.77}} = 0.926\ A$$

The output capacitor must have a current rating of at least 0.926 mA. The capacitor selected in this design was a 4.7 µF 50 V capacitor with a 1.5 A current rating.

Step 8 Selecting input capacitor. The input capacitor must be selected such that it provides a good filtering of the input voltage waveform. A good rule of thumb is to set the input voltage ripple ΔV_{IN} to be 1% of the minimum input voltage. The minimum input capacitor requirements are as follows:

$$C_{IN} = \frac{\Delta I_L}{8 \times f_{SW} \times \Delta V_{IN}} \quad (20)$$

$$= \frac{0.409}{8 \times 2\ MHz \times 0.05\ V} = 0.256\ \mu F$$

The rms current through the capacitor is given by:

$$I_{IN}\text{rms} = \frac{D + \frac{\Delta I_L}{I_{IN}(\max)}}{(1 - D(\max))\sqrt{12}} \quad (21)$$

$$= \frac{0.20 + \frac{0.409}{1.023}}{(1 - 0.77)\sqrt{12}} = 0.119\ A$$

A good ceramic input capacitor with ratings of 2.2 µF 50V or 4.7 µF 50 V will suffice for this application. Corresponding capacitors include:

Vendor	Value	Part number
Murata	4.7 µF 50 V	GRM32ER71H475KA88L
Murata	2.2 µF 50 V	GRM31CR71H225KA88L

Step 9 Choosing the input disconnect switch components. Set the input disconnect 1X current limit to 3 A by choosing a sense resistor. The calculated maximum value of the sense resistor is:

$$R_{SC}(\max) = V_{SENSEtrip} / 3.0\ A \quad (22)$$

$$= 0.098\ V / 3.0\ A = 0.033\ \Omega$$

The R_{SC} chosen is 0.03 Ω, a standard.

The trip point voltage must be:

$$V_{ADJ} = 3.0\ A \times 0.03\ \Omega = 0.090\ V$$

$$R_{ADJ} = (V_{SENSEtrip} - V_{ADJ}) / I_{ADJ} \quad (23)$$

$$R_{ADJ} = (0.098\ V - 0.09\ V) / 20.5\ \mu A = 390\ \Omega$$

A value of 383 Ω was chosen for this design.

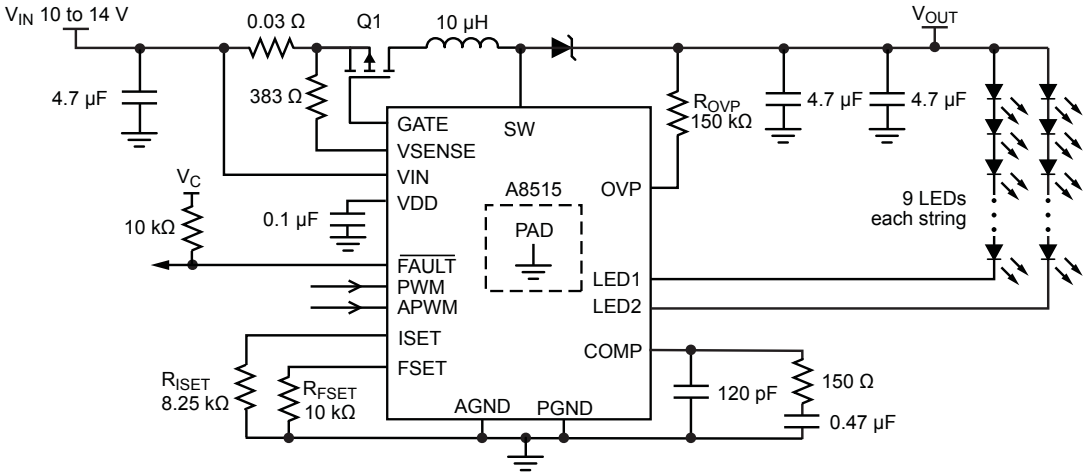


Figure 30. The schematic diagram showing calculated values from the design example above

Typical Application Circuits

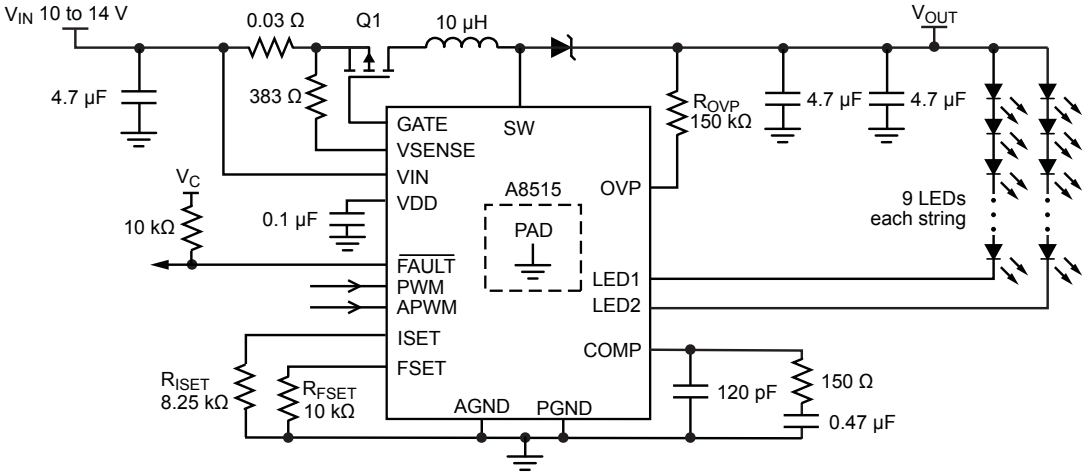


Figure 31. Typical application showing boost configuration, using current sensing and disconnect switch feature for an input of 12 V with an output to 18 LEDs (9 series LEDs in each of two strings) 120 mA current each LED

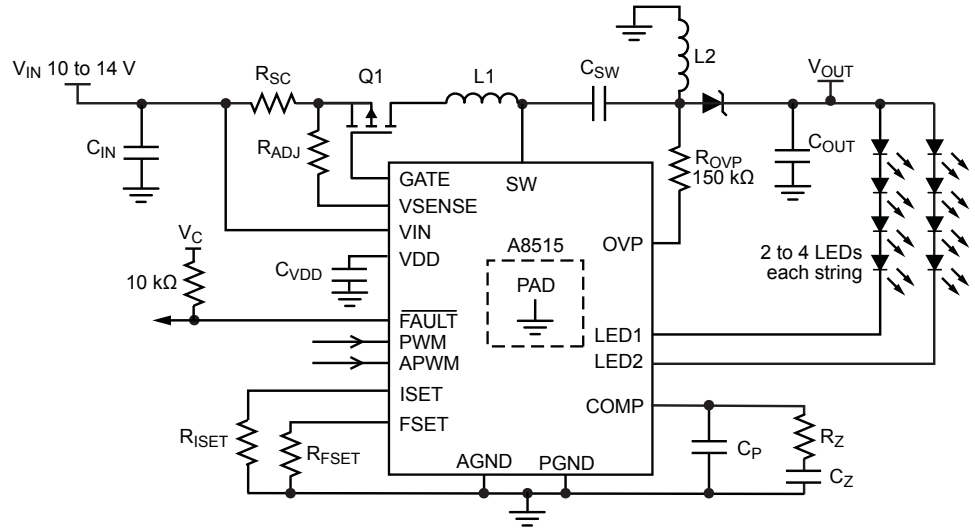
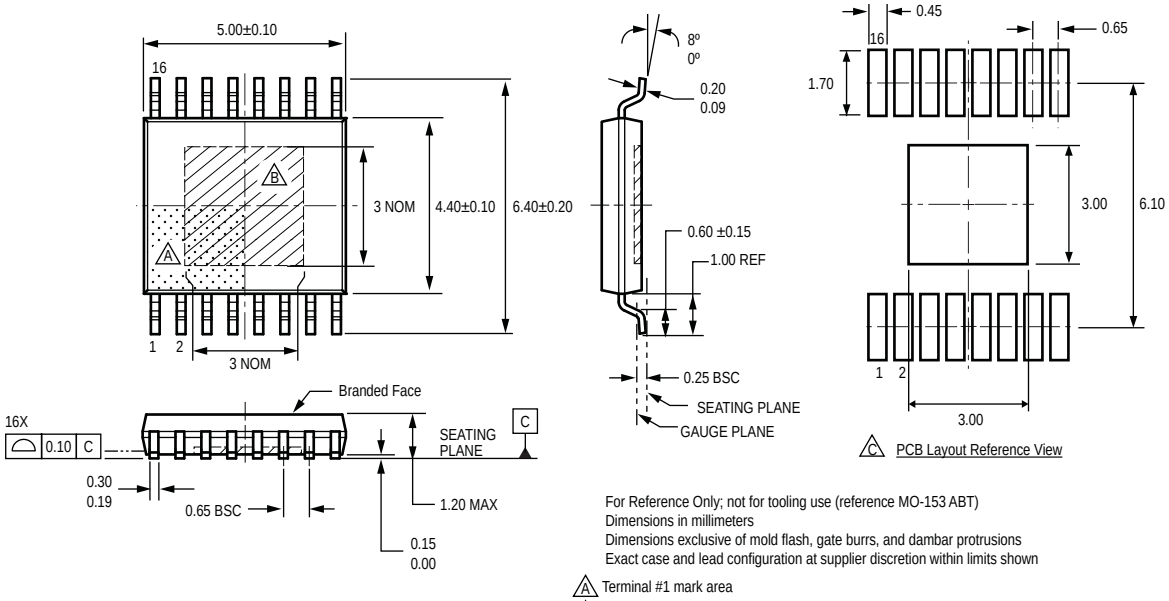


Figure 32. Typical application showing SEPIC configuration, with accurate input current sense, and VSENSE to GND protection

Package LP, 16-Pin TSSOP with Exposed Thermal Pad



For Reference Only; not for tooling use (reference MO-153 ABT)
Dimensions in millimeters
Dimensions exclusive of mold flash, gate burrs, and dambar protrusions
Exact case and lead configuration at supplier discretion within limits shown

A Terminal #1 mark area

B Exposed thermal pad (bottom surface); dimensions may vary with device

C Reference land pattern layout (reference IPC7351 SOP65P640X110-17M);
All pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)

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